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Nendai

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(54) **ORGANIC ELECTROLUMINESCENCE
DISPLAY PANEL AND METHOD OF
MANUFACTURING THE SAME**

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H01L 27/32 (2006.01)

H01L 51/00 (2006.01)

(52) **U.S. Cl.**

CPC **H01L 27/3246** (2013.01); **H01L 27/3211**
(2013.01); **H01L 51/0005** (2013.01); **H01L**
2227/323 (2013.01)

(58) **Field of Classification Search**

CPC H01L 27/3246; H01L 27/3211; H01L
51/0005; H01L 2227/323

See application file for complete search history.

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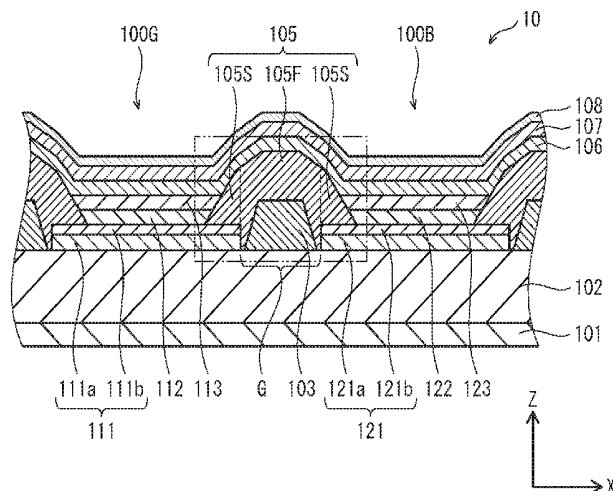
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P.L.C.

(57)

ABSTRACT

An organic EL display panel including: a substrate; a first lower electrode and a second lower electrode disposed over the substrate with a gap therebetween in a first direction; a wall separating a space above the first lower electrode and a space above the second lower electrode from one another; organic light-emitting layers respectively disposed in the spaces; and an upper electrode extending over the organic light-emitting layers. The wall includes a first portion disposed over the gap and two second portions each of which is disposed over a different one of the first lower electrode and the second lower electrode. The first portion is between the two second portions in the first direction, and at least a part of a bottom face of the first portion is positioned higher than a bottom face of the second portion.

9 Claims, 16 Drawing Sheets



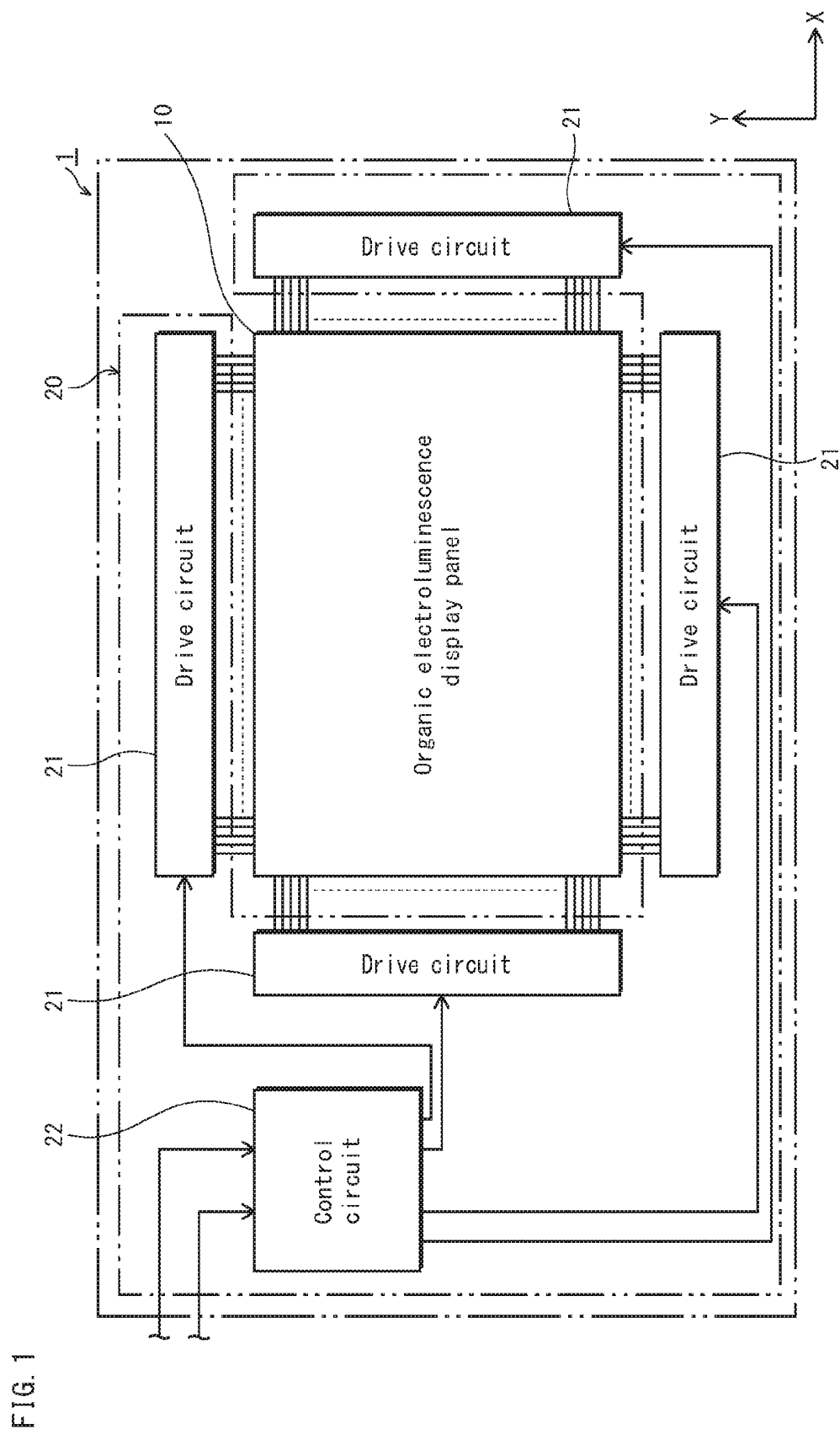


FIG. 2

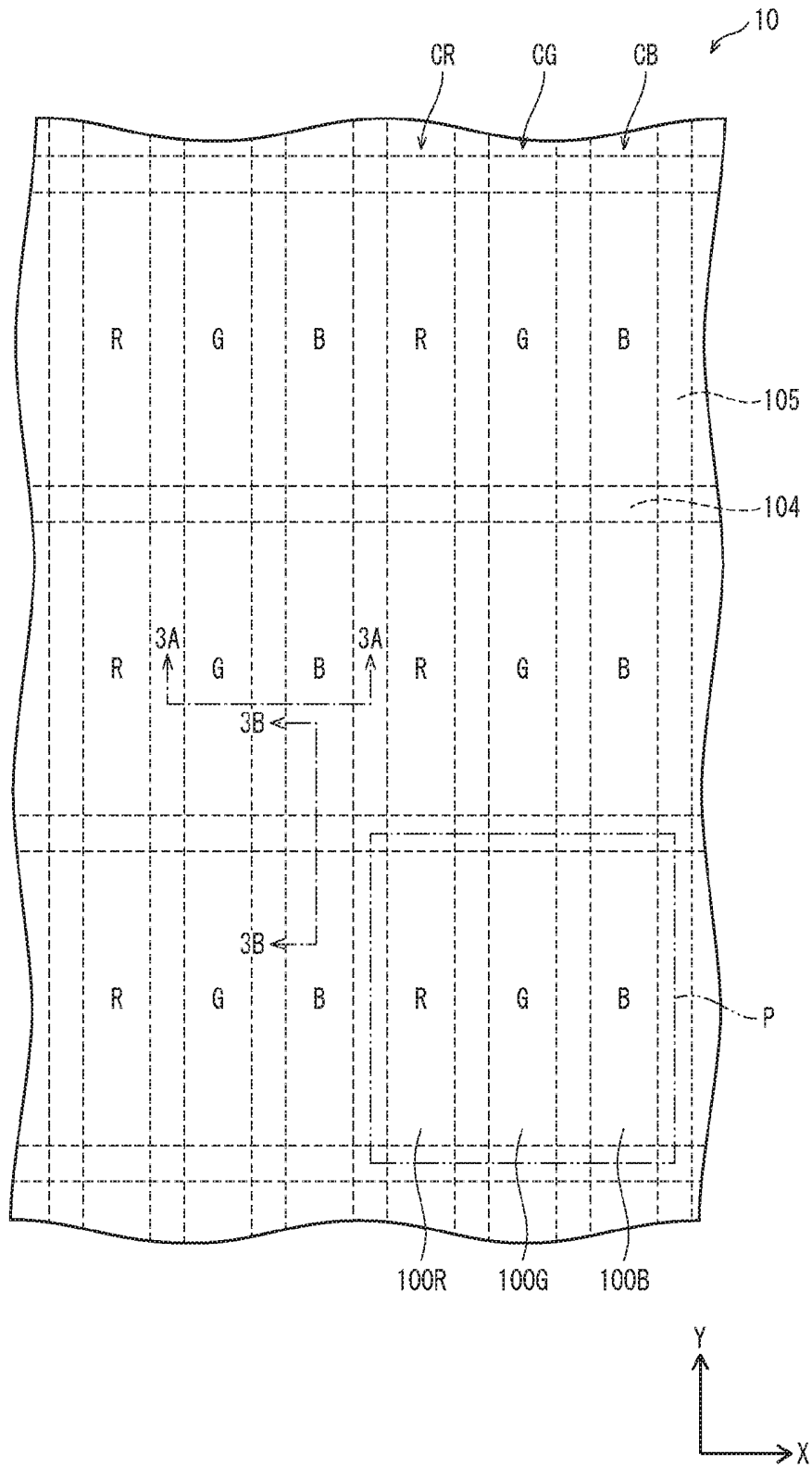


FIG. 3A

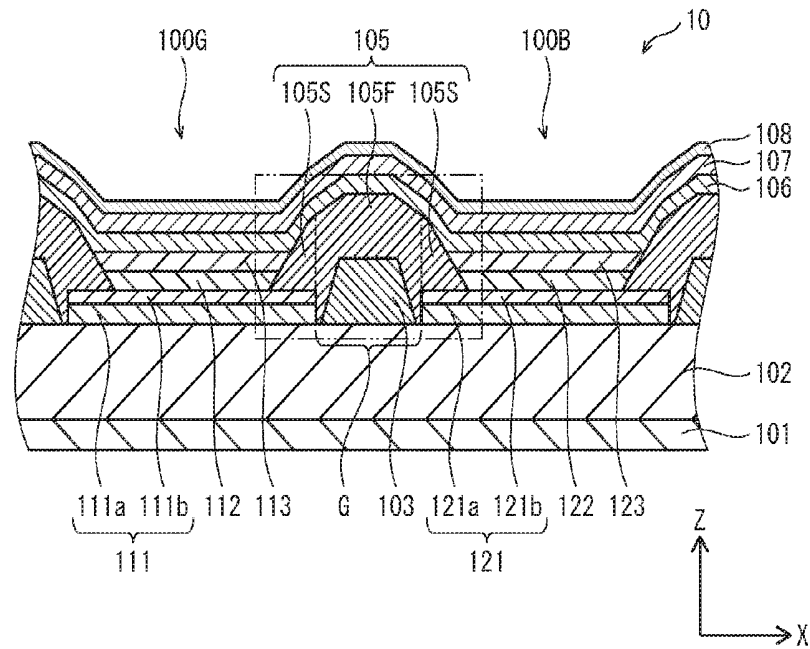


FIG. 3B

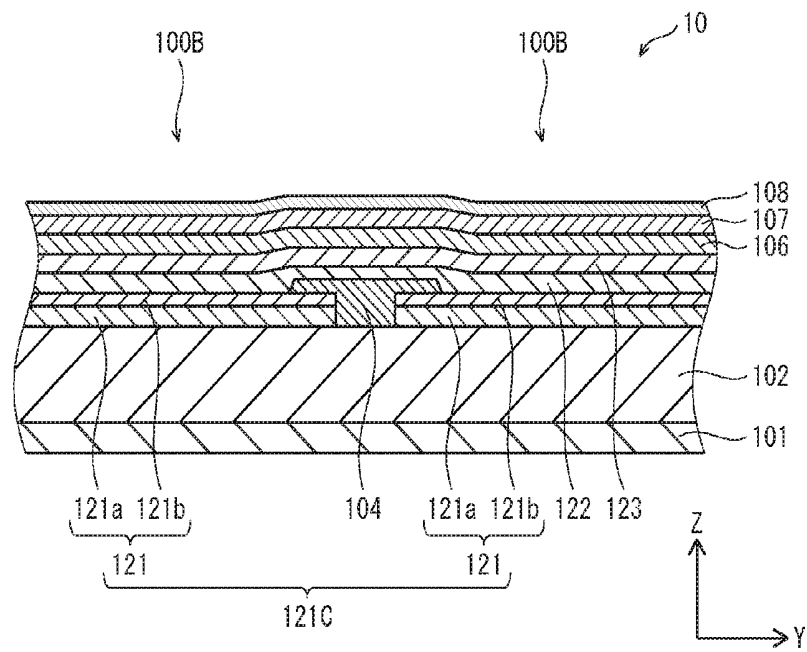


FIG. 4

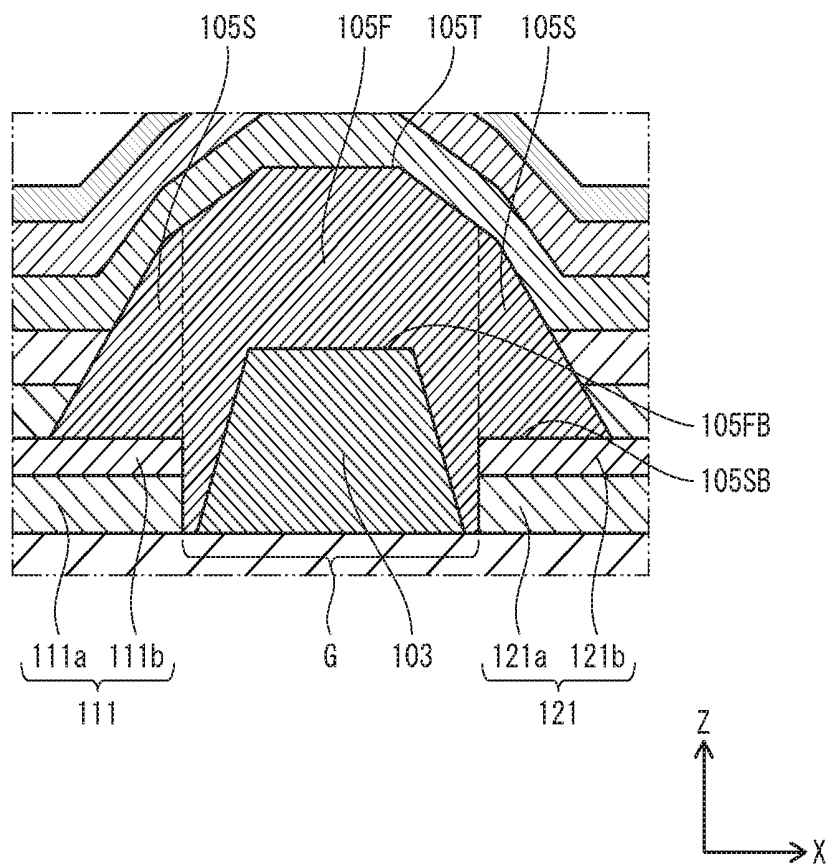


FIG. 5

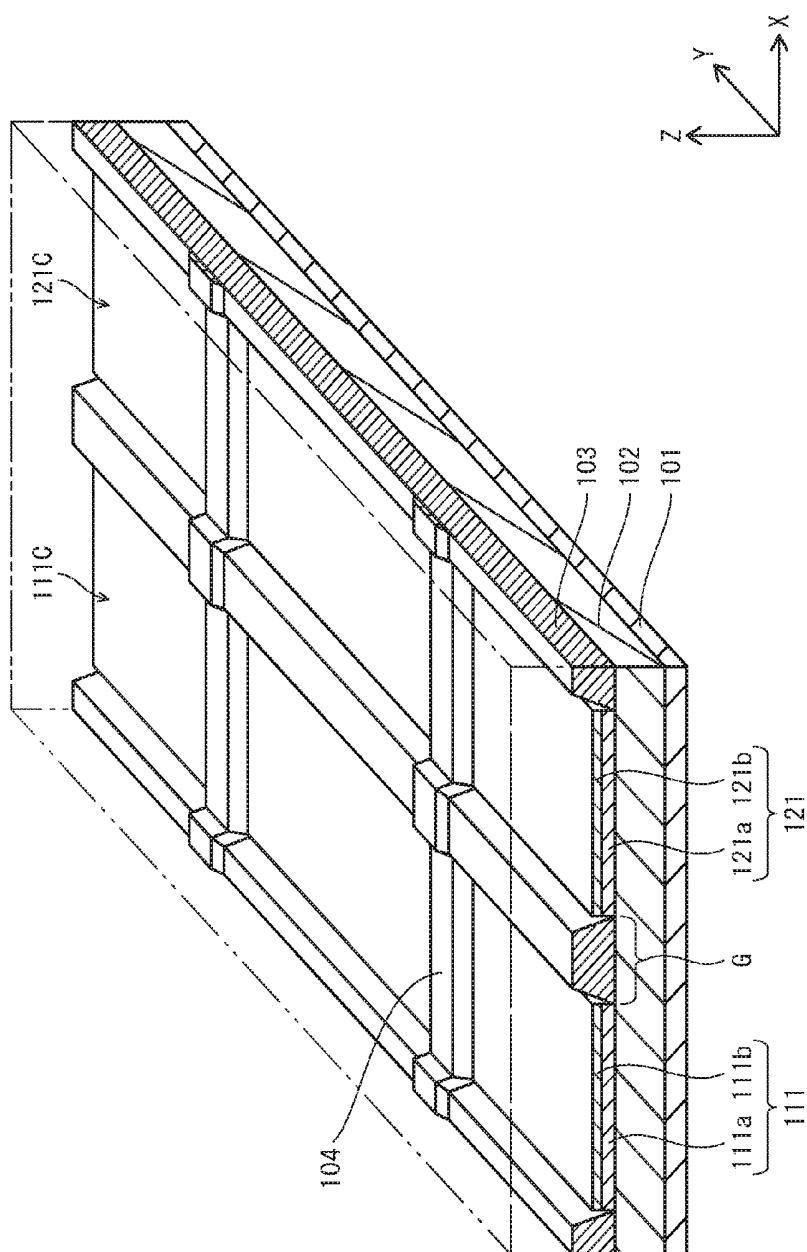


FIG. 6A

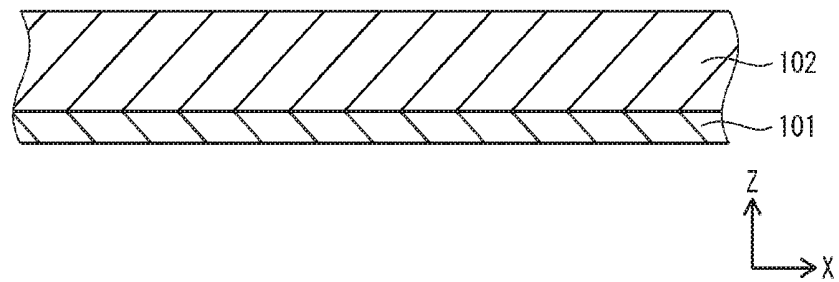


FIG. 6B

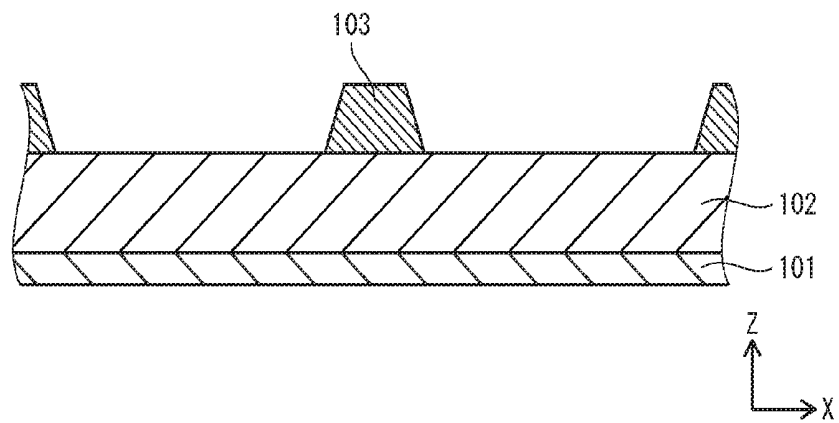


FIG. 6C

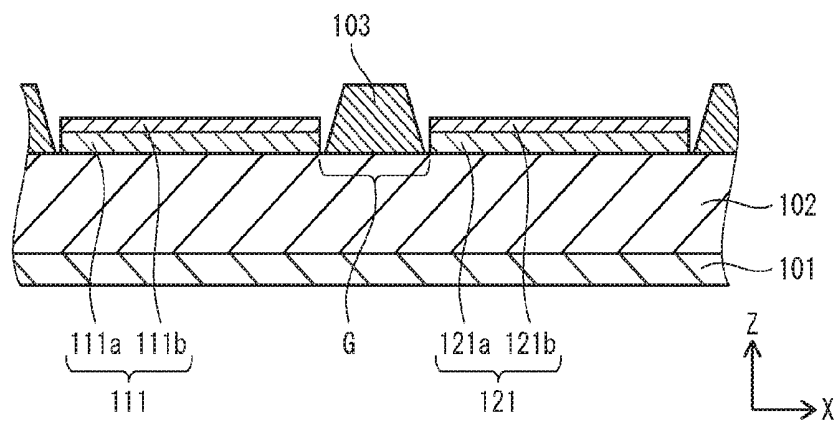


FIG. 7A

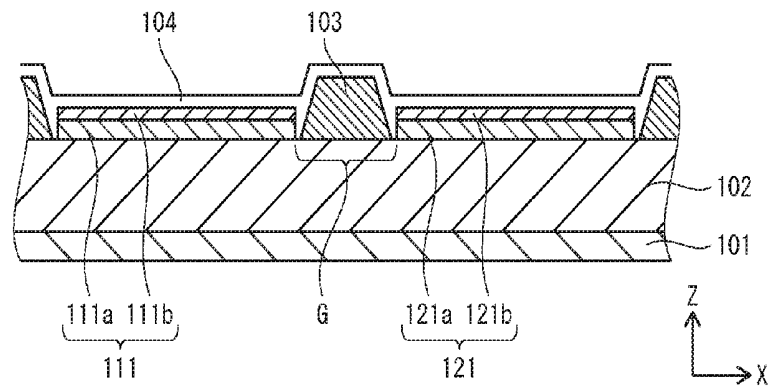


FIG. 7B

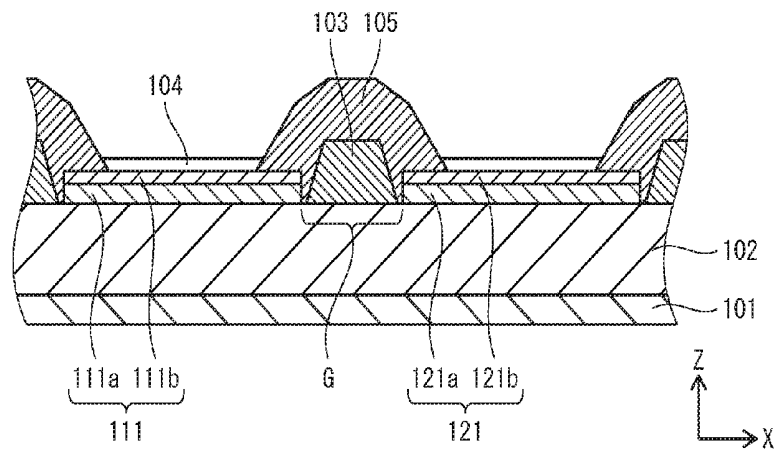


FIG. 7C

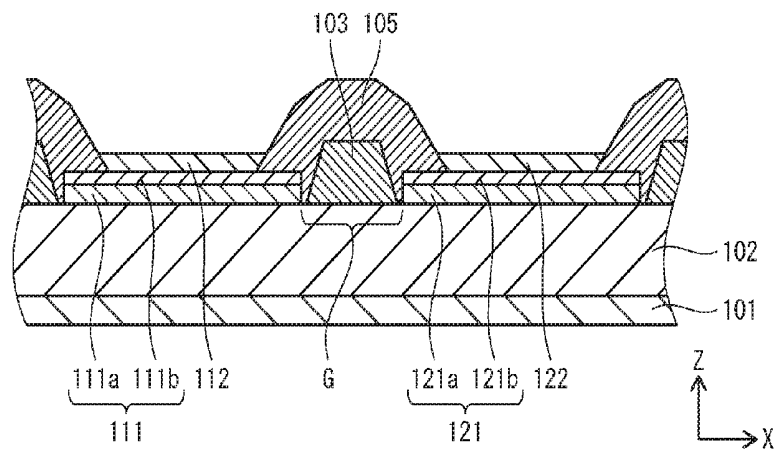


FIG. 8A

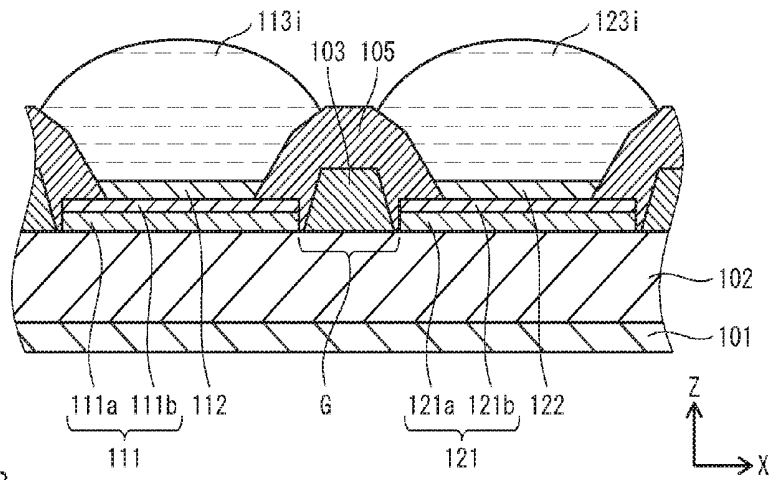


FIG. 8B

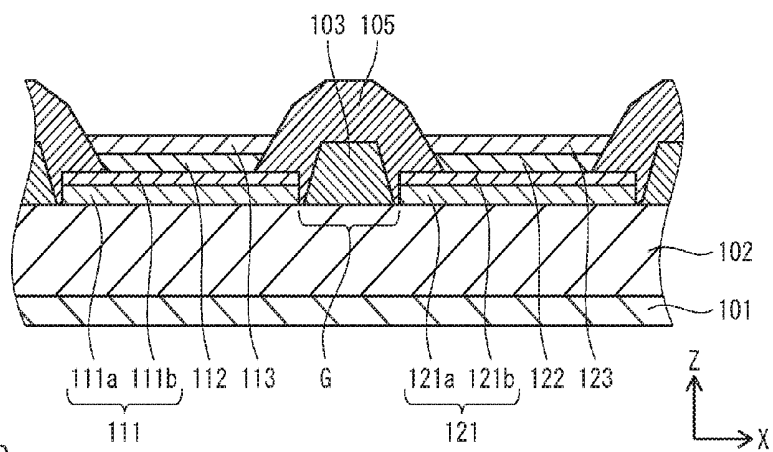


FIG. 8C

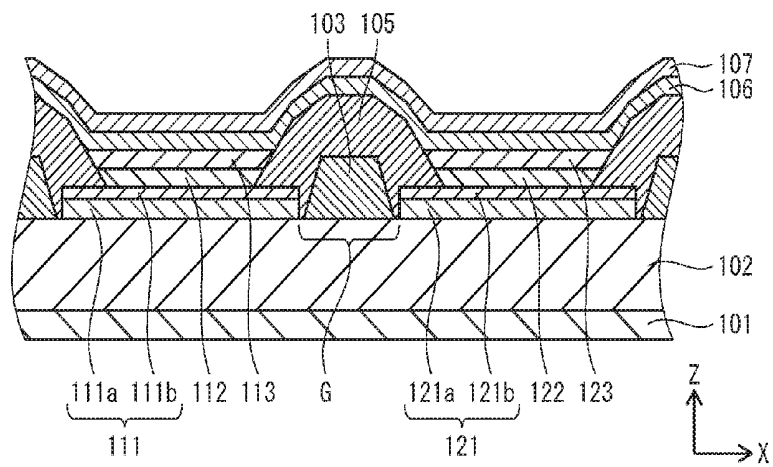


FIG. 9A

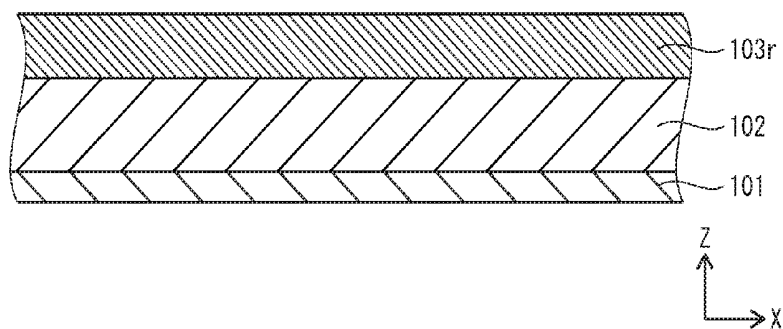


FIG. 9B

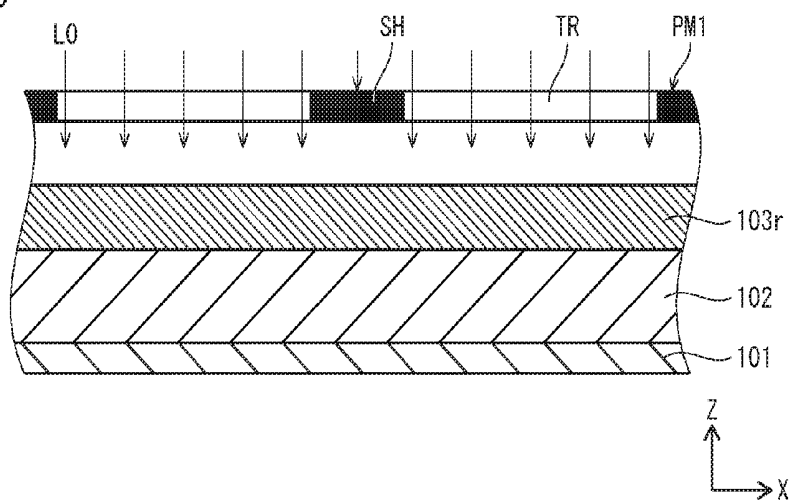


FIG. 9C

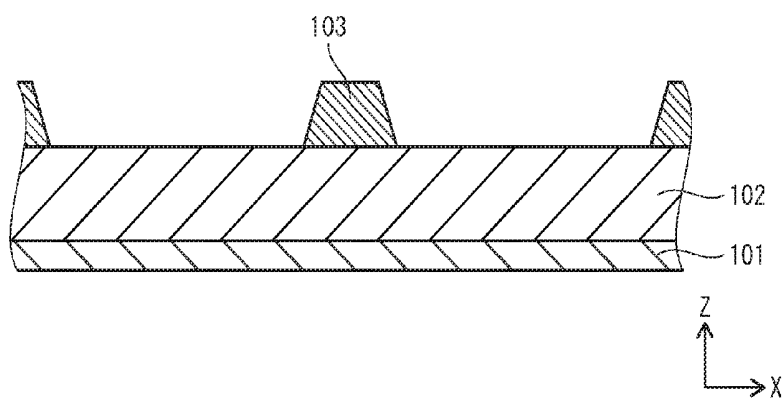


FIG. 10

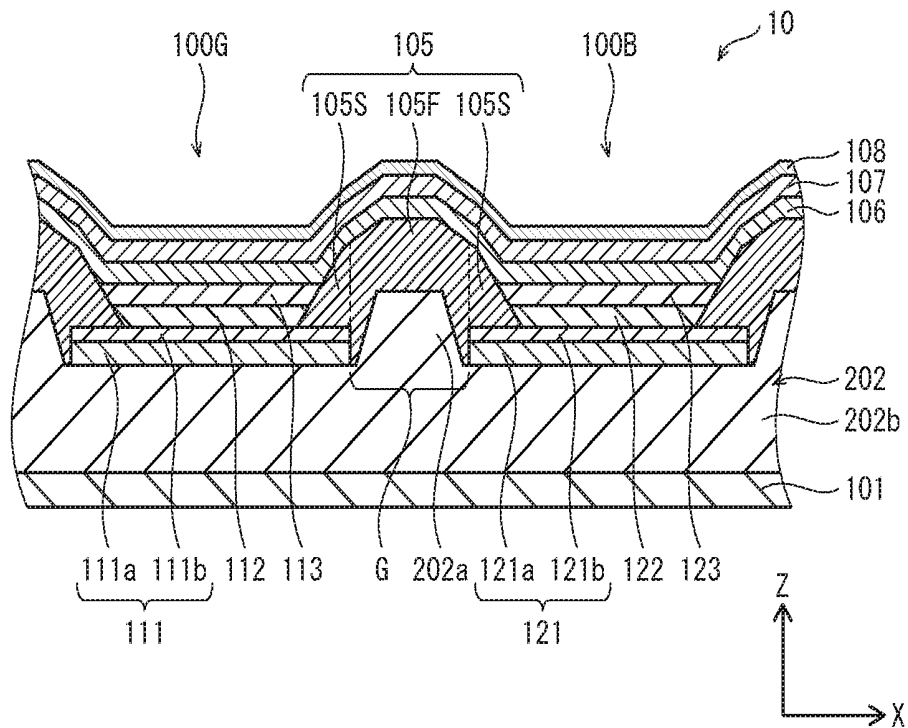


FIG. 11A

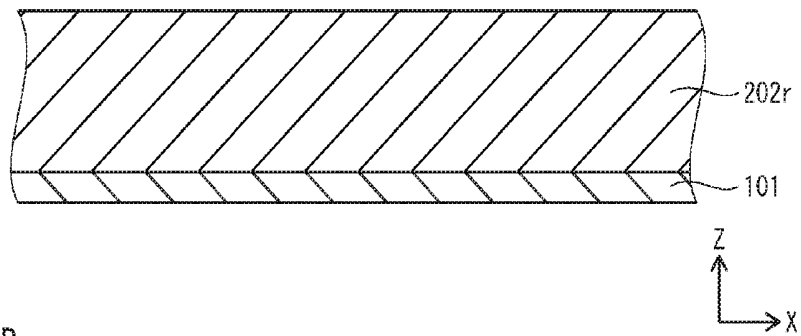


FIG. 11B

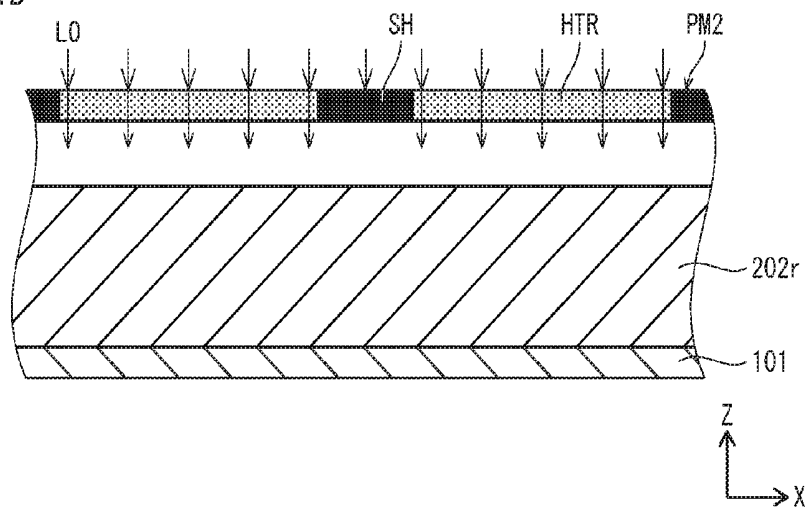


FIG. 11C

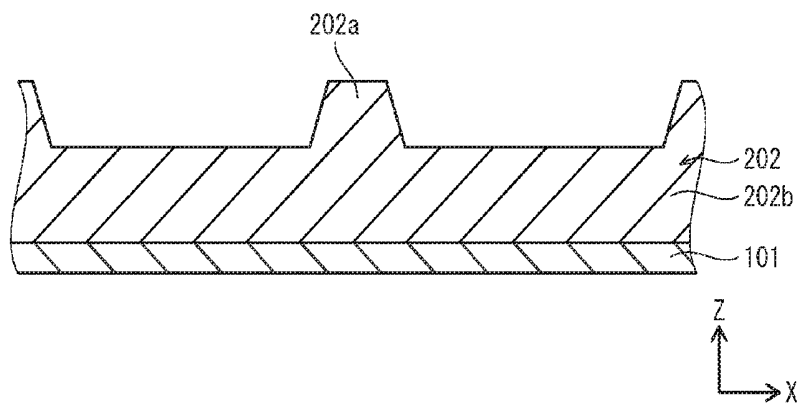


FIG. 12A

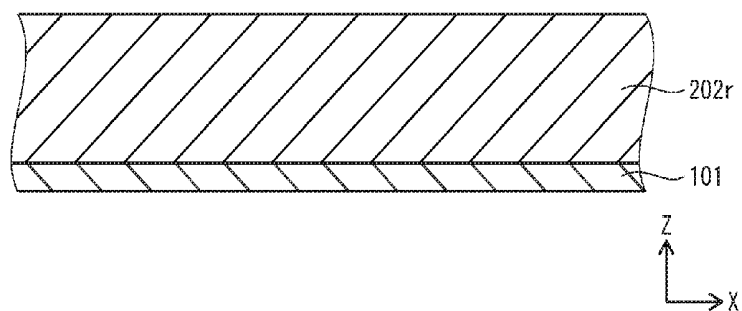


FIG. 12B

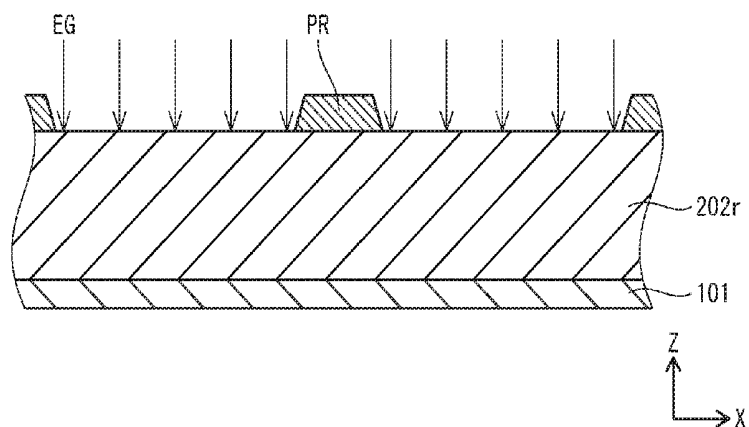
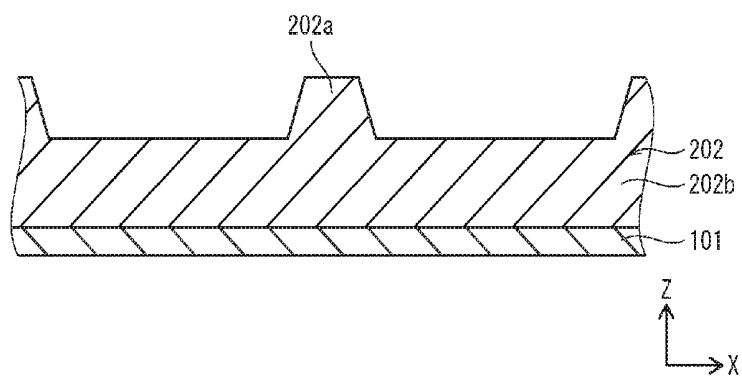


FIG. 12C



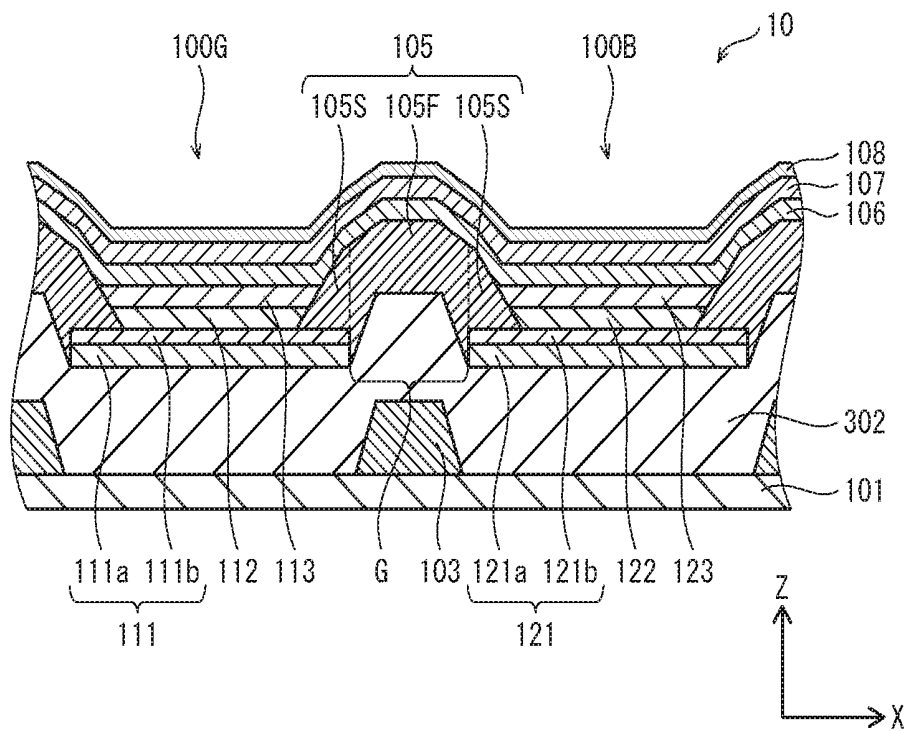


FIG. 14

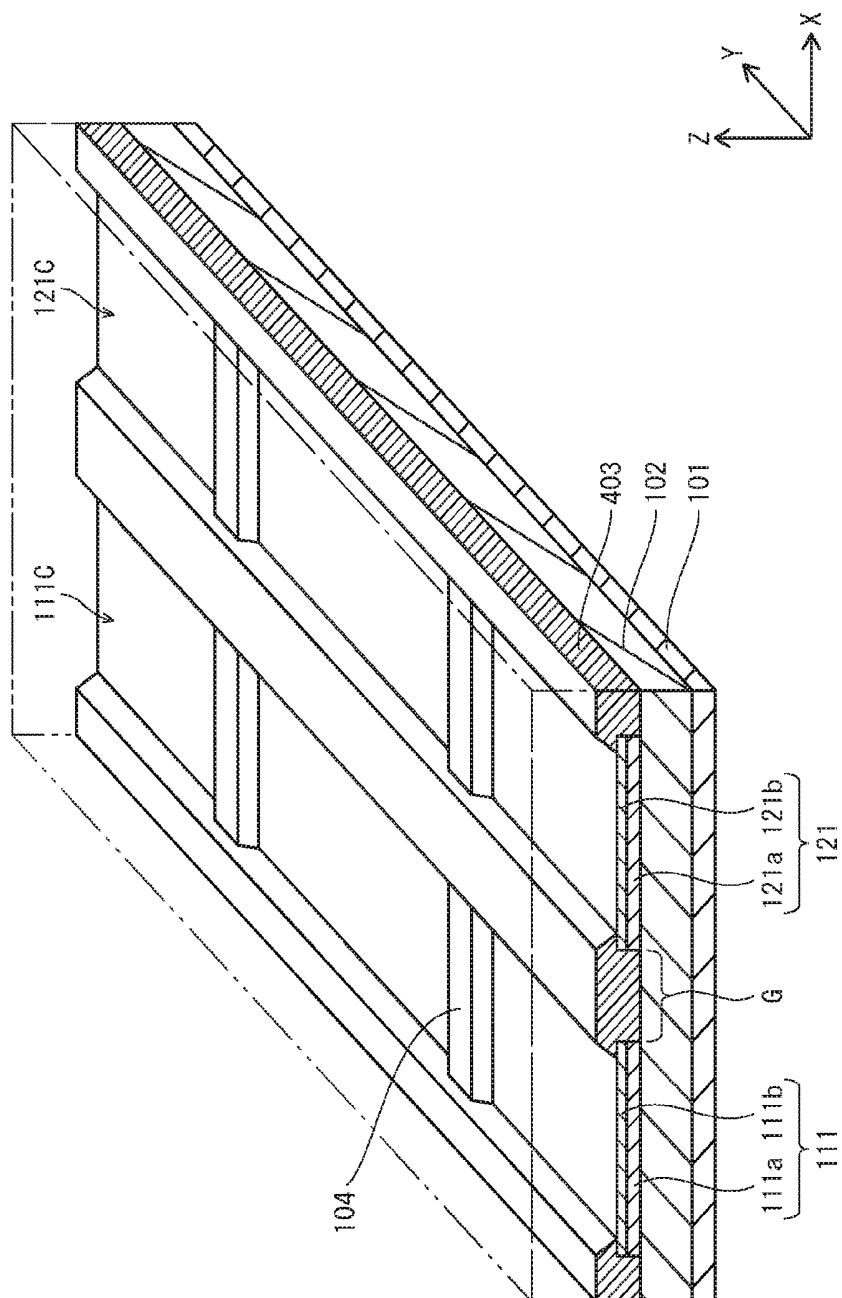


FIG. 15

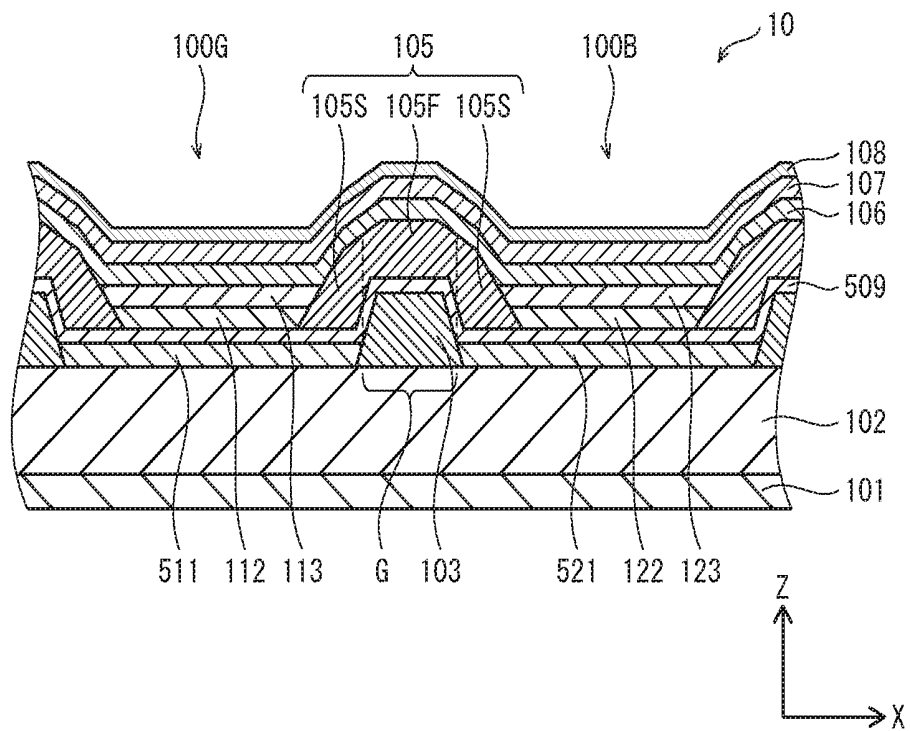


FIG. 16A

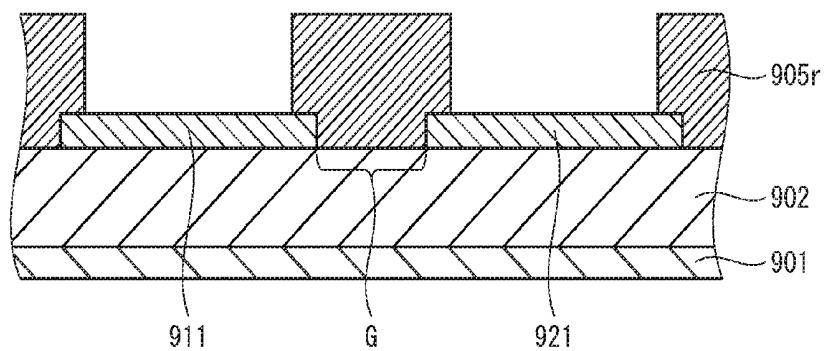


FIG. 16B

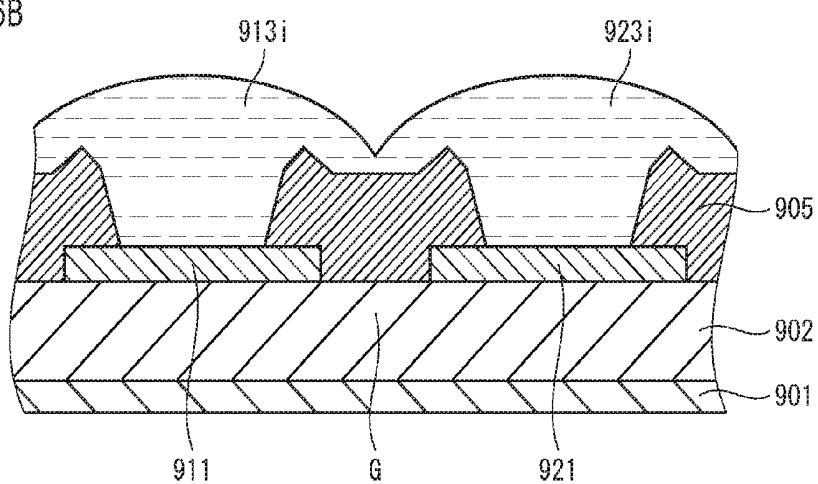
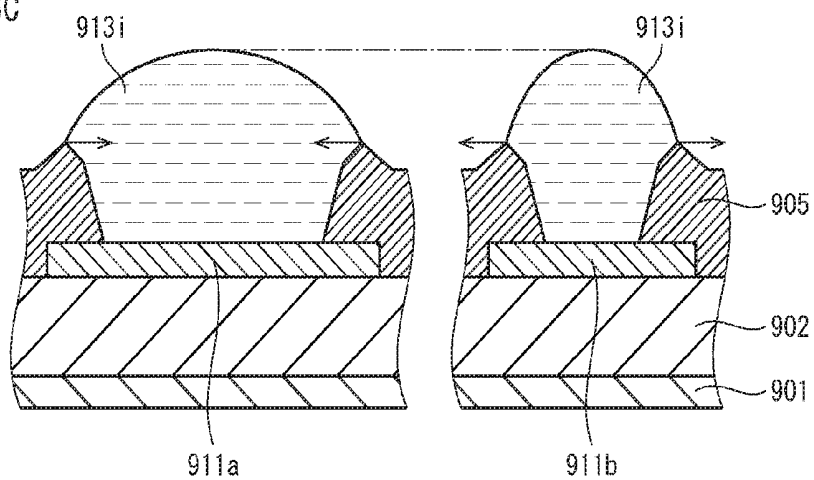


FIG. 16C



ORGANIC ELECTROLUMINESCENCE DISPLAY PANEL AND METHOD OF MANUFACTURING THE SAME

This application is based on an application No. 2014-250096 filed in Japan, the contents of which are hereby incorporated by reference.

BACKGROUND OF THE DISCLOSURE

(1) Technical Field

The present disclosure relates to an organic electroluminescence display panel and a manufacturing method therefor, and particularly pertains to partition wall formation technology.

(2) Description of Related Art

In recent years, the commodification of organic electroluminescence (hereinafter also EL) display panels using organic electroluminescence elements for emitting light has been advancing. In an organic electroluminescence display panel, a plurality of organic electroluminescence elements are arranged in a direction along a top face of a substrate serving as a support member, and an image is displayed through light emission by the organic light-emitting elements. Each organic electroluminescence element includes a lower electrode, an organic light-emitting layer that includes an organic light-emitting material, and an upper electrode, layered in the stated order on the substrate. Holes and electrons supplied by the lower electrode and the upper electrode are recombined in the organic light-emitting layer, thus causing the organic light-emitting material to emit light.

Among formation methods for the organic light-emitting layer, a wet process of forming the organic light-emitting layer by applying a solution (hereinafter, ink) in which the organic light-emitting material is dissolved in organic solvent, followed by drying, is superb technology for considerations of formation precision, material usage efficiency, and so on relating to the organic light-emitting layer. In this wet process, a partition wall shaped to partition ink application areas is used in order to constrain a decrease in formation precision of the organic light-emitting layer due to spread of unnecessary ink spills during application.

The partition wall is formed from an electrically insulating material. Typically, a resin material is used as the electrically insulating material. A typical method of forming the partition wall from the resin material involves applying the resin material, using a photolithography method or the like to perform patterning, and then curing (i.e., post-baking) (see, for example, Japanese Patent Application Publication No. 2008-287251, Japanese Patent Application Publication No. 2013-191483, and Japanese Patent Application Publication No. 2014-75260). The above-described curing improves adhesion between the partition wall and a foundation thereof, enables improvements in resistance to organic solvents for the partition wall, and constrains the penetration of developing fluid and ink into the partition wall (see, for example, Japanese Patent Application Publication No. 2008-287251 and Japanese Patent Application Publication No. 2013-191483). Also, in a situation where the partition wall includes liquid-repellent components, the curing displaces the liquid-repellent components toward the surface side. As such, this enables the liquid-repellent properties of the partition wall surface to be improved (see, for example, Japanese Patent Application Publication No. 2014-75260).

In addition, the above-described electrically insulating material may be silicon oxide or a similar inorganic material.

In such a situation, the partition wall is frequently formed using a dry process such as vacuum deposition or chemical vapor deposition (hereinafter, CVD).

SUMMARY OF THE DISCLOSURE

In the field of display panels, progress is being made in high-definition pixels, and the space between pixels is growing smaller. As such, running of applied ink beyond the partition wall is growing more common during the formation of the organic light-emitting layer. When such ink running occurs, the film thickness formation precision of the organic light-emitting layer is decreased, which leads to irregular color emission and brightness among the pixels as well as dead pixels, to decreases in useful light-emitting life, and so on. As such, the quality of the organic electroluminescence display panel is degraded.

Thus, an aim of the present disclosure is provide an organic electroluminescence display panel of stable quality, with a configuration in which ink running during organic light-emitting layer formation is unlikely, as well as a manufacturing method therefor.

In order to achieve this aim, one aspect of the present disclosure is an organic electroluminescence display panel, including: a substrate; a first lower electrode and a second lower electrode disposed over the substrate and spaced away from one another in a first direction along a top face of the substrate by a gap therebetween; a partition wall made of an electrically insulating material and separating a space above the first lower electrode and a space above the second lower electrode from one another, the partition wall including a first portion disposed over the gap and two second portions each of which is disposed over a different one of the first lower electrode and the second lower electrode, the first portion disposed between the two second portions in the first direction; a first organic light-emitting layer and a second organic light-emitting layer respectively disposed in the space above the first lower electrode and the space above the second lower electrode; and an upper electrode extending over the first organic light-emitting layer and the second organic light-emitting layer. In the organic electroluminescence display panel, at least a part of a bottom face of the first portion is positioned higher than a bottom face of the second portion.

Due to at least a part of the bottom face of the first portion being positioned higher than the bottom face of the second portion, the partition wall top face is constrained from sinking with respect to the first portion during formation of the partition wall. That is, the organic electroluminescence display panel has a configuration in which ink running during the formation of the organic light-emitting layer is unlikely, and provides stable quality.

BRIEF DESCRIPTION OF THE DRAWINGS

These and other objects, advantages, and features of the technology pertaining to the present disclosure will become apparent from the following description thereof taken in conjunction with the accompanying drawings, which illustrate at least one specific embodiment of the technology pertaining to the present disclosure.

FIG. 1 is a block diagram illustrating the overall configuration of an organic electroluminescence display device 1.

FIG. 2 is a schematic plan view diagram of a magnified portion of an image display face of the organic electroluminescence display panel 10.

FIG. 3A is a schematic cross-sectional diagram taken along line 3A-3A of FIG. 2, and FIG. 3B is a schematic cross-sectional diagram taken along line 3B-3B of FIG. 2.

FIG. 4 is a magnified view of the double-chained portion of FIG. 3A.

FIG. 5 is a schematic perspective view diagram illustrating a state of the organic electroluminescence display panel 10 prior to forming a partition wall 105.

FIGS. 6A 6B, and 6C are schematic cross-sectional diagrams illustrating a manufacturing process of the organic electroluminescence display panel 10, where FIG. 6A illustrates formation of an inter-layer insulation layer, FIG. 6B illustrates formation of a convex layer, and FIG. 6C illustrates formation of a lower electrode.

FIGS. 7A 7B, and 7C are schematic cross-sectional diagrams illustrating the manufacturing process of the organic electroluminescence display panel 10, where FIG. 7A illustrates formation of a pixel insulation layer, FIG. 7B illustrates formation of the partition wall, and FIG. 7C illustrates formation of a hole transport layer.

FIGS. 8A 8B, and 8C are schematic cross-sectional diagrams illustrating the manufacturing process of the organic electroluminescence display panel 10, where FIG. 8A illustrates ink application during formation of an organic light-emitting layer, FIG. 8B illustrates ink drying during the formation of the organic light-emitting layer, and FIG. 8C illustrates formation of an electron transport layer and an upper electrode.

FIGS. 9A 9B, and 9C are schematic cross-sectional diagrams illustrating a formation process of the convex layer 103, where FIG. 9A illustrates application of a resin material, FIG. 9B illustrates exposure, and FIG. 9C illustrates developing.

FIG. 10 is a schematic cross-sectional diagram illustrating an inter-layer insulation layer 202 pertaining to a variation.

FIGS. 11A, 11B, and 11C are schematic cross-sectional diagrams illustrating a formation process of the inter-layer insulation layer 202, where FIG. 11A illustrates application of a resin material, FIG. 11B illustrates exposure, and FIG. 11C illustrates developing.

FIGS. 12A, 12B, and 12C are schematic cross-sectional diagrams illustrating a formation process of the inter-layer insulation layer 202, where FIG. 12A illustrates application of a resin material, FIG. 12B illustrates dry etching, and FIG. 12C illustrates resist peeling.

FIG. 13 is a schematic cross-sectional diagram illustrating an inter-layer insulation layer 302 pertaining to a variation.

FIG. 14 is a schematic perspective view diagram illustrating a convex layer 403 pertaining to a variation.

FIG. 15 is a schematic cross-sectional diagram illustrating a hole injection layer 509 pertaining to a variation.

FIGS. 16A, 16B, and 16C are schematic cross-sectional diagrams explaining ink running in organic electroluminescence display panels, where FIG. 16A illustrates a resin material immediately after patterning, FIG. 16B illustrates the effect of partition wall shape on ink application, and FIG. 16C illustrates the effect of pixel spacing on ink application.

BACKGROUND LEADING TO THE DISCLOSURE

The inventor of the present disclosure (hereinafter also termed the present inventor) has discovered that the shape of partition walls is an issue in the advancement of high-definition organic electroluminescence display panels equipped with an organic light-emitting layer formed by a wet process. This issue is described with reference to FIGS.

16A, 16B, and 16C. FIGS. 16A, 16B, and 16C are schematic cross-sectional diagrams intended to explain the running of ink in an organic electroluminescence display panel. In the following, description is provided taking as an example an organic electroluminescence display panel having pixels realizing full color display, due to the pixels each being composed of sub-pixels that respectively emit light in one of red, blue, and green and that are each configured by using an organic electroluminescence element.

FIGS. 16A and 16B illustrate cross-sections in which neighboring sub-pixels are aligned. A first lower electrode 911 and a second lower electrode 921 are disposed over a substrate 901 having an inter-layer insulation layer 902 arranged thereon. The first lower electrode 911 and the second lower electrode 921 are aligned along a first direction (the lateral direction on the page) above a top face of the substrate 901, with a gap G therebetween. Also, as illustrated in FIG. 16B, a partition wall 905 is arranged over the gap G. The partition wall 905 separates a space above the first lower electrode 911 and a space above the second lower electrode 921 from one another. The partition wall 905 takes up a formation margin taking an alignment margin into consideration. As such, the partition wall 905 is formed not only with a portion above the gap G but also with portions above the lower electrodes 911, 921 neighboring the portion above the gap G in the first direction.

Here, as illustrated in FIG. 16A, in a situation where the partition wall 905 is formed from a resin material 905r, a top face of the resin material 905r immediately after patterning performed by a photolithography method conforms to the shape at application and is flat above the first lower electrode 901, above the gap G, and above the second lower electrode 921.

However, as illustrated in FIG. 16B, the present inventor has discovered that, upon curing the resin material 905r, the top face of the partition wall 905 takes on a shape, after curing, that conforms to irregularities on a bottom face of the partition wall 905. Specifically, the curing causes shrinkage of the resin material 905r. Thus, the present inventor has discovered that the top face of the partition wall 905 conforms to a concavity in the bottom face of the partition wall 905 at the gap G, sinks above the gap G, and takes on a concave shape.

In such circumstances, the height of the partition wall 905 becomes greatest at parts of the partition wall 905 facing the first lower electrode 911 and the second lower electrode 921. As such, ink 913i and ink 923i, each applied between a pair of partition walls 905, is easily able to cross the highest points of the partition walls 905. Also, in a situation where the partition walls 905 have a concave shape, the ink 913 and the ink 923i crossing the highest points spread over the top faces of the partition walls 905, and it is likely that the ink 913i and the ink 923i come in contact and combine, spilling over the partition walls 905. As such, the partition wall 905 having a concave top face is prone to ink running.

Particularly, the above-described concave partition wall is a point of concern regarding advances in high-definition organic electroluminescence display panels. For example, FIG. 16C illustrates the effect that pixel spacing has in applying ink 913i having identical liquid level height. Specifically, the pixel separation is narrowed at high definition, and due to this, the lower electrode 911b on the right-hand side is narrower than the lower electrode 911a on the left-hand side in FIG. 16C.

On the left-hand side of FIG. 16C, sufficient spacing is secured between the partition walls 905 with respect to the liquid level height of the ink 913i. That is, a half-oval joining

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the liquid level of the ink 913i and the highest points of partition walls 905 has a minor axis in the height direction and a major axis in the width direction. The surface tension of the ink 913i pulls toward the inner side of the ink 913i, as indicated by the arrows. Accordingly, the ink 913i is unlikely to cross the partition walls 905 on the left-hand side of FIG. 16C.

Conversely, on the right-hand side of FIG. 16C, the spacing between the partition walls 905 is insufficient with respect to the liquid level height of the ink 913i. That is, a half-oval joining the liquid level of the ink 913i and the highest points of partition walls 905 has a major axis in the height direction and a minor axis in the width direction. The surface tension of the ink 913i pulls toward the outer side of the ink 913i, as indicated by the arrows. Accordingly, the ink 913i easily crosses the highest points of the partition walls 905 and is prone to running on the right-hand side of FIG. 16C.

Thus, as illustrated on the left-hand side of FIG. 16C, the liquid level height of the ink 913i had not previously been an issue despite the presence of a concave top face of the partition wall 905. However, as advances in definition are made, the possibility of ink running occurring as illustrated on the right-hand side of FIG. 16C increases.

Also, the concave shape of the top face of the partition wall 905 occurs not only when the partition wall 905 is formed from the resin material 905r, but also when the partition wall 905 is formed from an inorganic material. This is because forming the partition wall 905 from an inorganic material involves a dry process. Thus, unlike FIG. 16A, the top face of the partition wall 905 reflects irregularities at the bottom face immediately after patterning (film formation), and sinking occurs over the gap G.

Accordingly, the partition wall 905 having the portion over the gap G and the portions over the lower electrodes 911, 921 neighboring that portion on both sides is prone to top face sinking over the gap G irrespective of whether the material used is a resin material or an inorganic material, as the top face takes on a concave shape.

One approach to constraining the running of ink is simply to increase the film thickness and raise the overall height of the partition wall. However, this method does not avoid the sinking of the top face of the partition wall over the gap G and the concavity of the top face where the ink is prone to flowing out remain as it is. Thus, the partition wall must be made excessively tall in order to constrain ink running. In such a situation, aside from posing difficulties in thinning the organic electroluminescence display panel, a great difference in height is produced over a short distance from the top faces of the lower electrodes to the highest points of the partition walls. As such, upper layers such as an upper electrode are prone to cracks, tier cutting, and so on.

According to the above, with focus on high definition organic electroluminescence display panels, and as a result of consideration of a configuration in which ink running is unlikely, that is, of an organic electroluminescence display panel in which sinking of the top face of the partition wall is constrained, the present inventor has arrived at aspects of the disclosure as described below.

DESCRIPTION OF EMBODIMENT

One aspect of the present disclosure is an organic electroluminescence display panel, including: a substrate; a first lower electrode and a second lower electrode disposed over the substrate and spaced away from one another in a first direction along a top face of the substrate by a gap therebe-

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tween; a partition wall made of an electrically insulating material and separating a space above the first lower electrode and a space above the second lower electrode from one another, the partition wall including a first portion disposed over the gap and two second portions each of which is disposed over a different one of the first lower electrode and the second lower electrode, the first portion disposed between the two second portions in the first direction; a first organic light-emitting layer and a second organic light-emitting layer respectively disposed in the space above the first lower electrode and the space above the second lower electrode; and an upper electrode extending over the first organic light-emitting layer and the second organic light-emitting layer. In the organic electroluminescence display panel, at least a part of a bottom face of the first portion is positioned higher than a bottom face of the second portion.

The organic electroluminescence display panel pertaining to one aspect of the present disclosure has at least part of the bottom face of the first portion positioned higher than the bottom face of the second portion. As such, sinking of the partition wall top face is constrained with respect to the first portion during formation of the partition wall. That is, the organic electroluminescence display panel has a configuration in which ink running is unlikely, and provides stable quality.

In the organic electroluminescence display panel pertaining to one aspect of the present disclosure, in the first direction, a central part of the bottom face of the first portion may be positioned higher than the bottom face of the second portion.

Accordingly, the center portion of the bottom face of the first portion in the first direction, where the top face is most prone to sinking, is positioned higher than the bottom face of the second portion. As such, the sinking of the partition wall top face is effectively constrained.

The organic electroluminescence display panel pertaining to one aspect of the present disclosure may further include a convex layer made of an electrically insulating material between the substrate and the first portion, having greater thickness than the first lower electrode and the second lower electrode.

Accordingly, a part of the foundation of the partition wall below the first portion protrudes upward with respect to a part of the foundation below the second portion. As such, the bottom face of the first portion, above the convex layer, is positioned higher than the bottom face of the second portion.

The organic electroluminescence display panel pertaining to one aspect of the present disclosure may further include an inter-layer insulating layer made of a resin material and disposed over the substrate, a shape of a top face of the inter-layer insulating layer in conformity with a shape of the top face of the substrate, the convex layer may be made of the resin material, and the first lower electrode, the second lower electrode, and the convex layer may be disposed over the inter-layer insulating layer.

The organic electroluminescence display panel pertaining to one aspect of the present disclosure may further include an inter-layer insulating layer made of a resin material and disposed over the substrate and the convex layer, a shape of a top face of the inter-layer insulating layer in conformity with a combination of a shape of the top face of the substrate and a top face of the convex layer, the convex layer may be made of the resin material, and the first lower electrode and the second lower electrode may be disposed over the inter-layer insulating layer.

Accordingly, the convex layer is formed from the same resin material as the inter-layer insulation layer. During the

formation of the convex layer, the material, equipment, technology, and so on used in forming the inter-layer insulation layer may be re-used, enabling any decrease in manufacturing efficiency caused by the addition of the convex layer to be constrained.

The organic electroluminescence display panel pertaining to one aspect of the present disclosure may further include an inter-layer insulating layer made of a resin material and disposed over the substrate, a shape of a top face of the inter-layer insulating layer in conformity with a shape of the top face of the substrate, and the inter-layer insulating layer may include a planar portion on which the first lower electrode and the second lower electrode are disposed and a convex portion on the planar portion, the convex portion corresponding in position to the gap and protruding upward higher than a top face of the first lower electrode and a top face of the second lower electrode.

Accordingly, a part of the foundation of the partition wall below the first portion protrudes upward with respect to a part of the foundation below the second portion. As such, at least part of the bottom face is positioned higher than other parts of the bottom face.

In the organic electroluminescence display panel pertaining to one aspect of the present disclosure, in a second direction that is along the top face of the substrate and that is perpendicular to the first direction, the first lower electrode may be provided in plurality to form a line of first lower electrodes, and the second lower electrode may be provided in plurality of form a line of second lower electrodes, the first organic light-emitting layer may extend in the second direction over the line of first lower electrodes, and the second organic light-emitting layer may extend in the second direction over the line of second lower electrodes, and the partition wall may extend in the second direction between the first organic light-emitting layer and the second organic light-emitting layer, and in any cross-section taken along the second direction, at least a part of the bottom face of the first portion may be positioned higher than the bottom face of the second portion.

Accordingly, sinking of the top face of the partition wall is constrained at the first portion during the formation of the partition wall, along the second direction. That is, the organic electroluminescence display panel has a configuration in which ink running is unlikely across the second direction, and further provides stable quality.

The organic electroluminescence display panel pertaining to one aspect of the present disclosure may further include a convex layer formed from an electrically insulating material, disposed between the substrate and the first portion, and extending in the second direction, and the convex layer may have greater thickness than the first lower electrodes and the second lower electrodes.

Accordingly, a part of the foundation of the partition wall below the first portion protrudes upward with respect to a part of the foundation below the second portion. As such, at least part of the bottom face is positioned higher than other parts of the bottom face, in a lateral cross-section of the partition wall along the second direction.

The organic electroluminescence display panel pertaining to one aspect of the present disclosure may further include a pixel insulation layer formed from an electrically insulating material, extending in the first direction, and disposed between electrodes adjacent in the second direction, the electrodes adjacent in the second direction comprising a combination of two first lower electrodes and a combination of two second lower electrodes, and the pixel insulation

layer has greater thickness than the first lower electrodes and the second lower electrodes, and has smaller thickness than the convex layer.

Accordingly, providing the pixel insulation layer enables improvements to the electrical insulation between neighboring pairs of the first lower electrodes and second lower electrodes, constrains tier cutting of the first organic light-emitting layer and the second organic light-emitting layer, and enables improvements to the electrical insulation between the first lower electrodes, the second lower electrodes, and the upper electrode.

In the organic electroluminescence display panel pertaining to one aspect of the present disclosure, the convex layer and the pixel insulation layer may form a single layer.

Accordingly, the convex layer and the pixel insulation layer may be formed simultaneously, enabling any decrease in manufacturing efficiency caused by the addition of the convex layer to be constrained.

In the organic electroluminescence display panel pertaining to one aspect of the present disclosure, a color of light emitted by the first organic light-emitting layer may differ from a color of light emitted by the second organic light-emitting layer.

Accordingly, not only decreases in film thickness formation precision but also mixing (color combination) of ink including different organic light-emitting materials may be constrained, and any decrease in quality of the organic electroluminescence display panel, such as faulty color emission of pixels, may also be constrained.

One aspect of the present disclosure is an organic electroluminescence display panel manufacturing method, including: preparing a substrate; forming a first lower electrode and a second lower electrode disposed over the substrate and spaced away from one another in a first direction along a top face of the substrate by a gap therebetween; forming a partition wall by using an electrically insulating material, the partition wall separating a space above the first lower electrode and a space above the second lower electrode from one another and including a first portion disposed over the gap and two second portions each of which being disposed over a different one of the first lower electrode and the second lower electrode, the first portion disposed between the two second portions in the first direction; performing a wet process to form a first organic light-emitting layer and a second organic light-emitting layer in the space above the first lower electrode and the space above the second lower electrode, respectively; and forming an upper electrode extending over the first organic light-emitting layer and the second organic light-emitting layer. In the organic electroluminescence display panel manufacturing method, at least a part of a bottom face of the first portion is positioned higher than a bottom face of the second portion.

According to the organic electroluminescence display panel manufacturing method pertaining to one aspect of the present disclosure, sinking of the partition wall top face over the first portion is constrained during formation of the partition wall, and ink running is unlikely to occur during formation of the organic light-emitting layers. As such, the quality of the manufactured organic electroluminescence display panel is stabilized.

The organic electroluminescence display panel manufacturing method pertaining to one aspect of the present disclosure may further include, before forming the first lower electrode and the second lower electrode: forming an inter-layer insulating layer over the substrate by using a resin material, a shape of a top face of the inter-layer insulating

layer in conformity with a shape of the top face of the substrate; and forming a convex layer over the interlayer-insulating layer by using the resin material, the convex layer extending in a second direction that is along the top face of the substrate and that is perpendicular to the first direction, and the first lower electrode and the second lower electrode may be formed over the inter-layer insulating layer at opposite sides of the convex layer in the first direction and each with smaller thickness than the convex layer, such that at least a part of the bottom face of the first portion is positioned higher than the bottom face of the second portion.

The organic electroluminescence display panel manufacturing method pertaining to one aspect of the present disclosure may further include, before forming the first lower electrode and the second lower electrode: forming a convex layer over the substrate by using a resin material, the convex layer extending in a second direction that is along the top face of the substrate and that is perpendicular to the first direction; and forming an inter-layer insulating layer over the substrate and the convex layer by using the resin material, a shape of a top face of the inter-layer insulating layer in conformity with a combination of a shape of the top face of the substrate and a top face of the convex layer, and the first lower electrode and the second lower electrode may be formed over the inter-layer insulating layer at opposite sides of the convex layer in the first direction and each with smaller thickness than the convex layer, such that at least a part of the bottom face of the first portion is positioned higher than the bottom face of the second portion.

Accordingly, at least a part of the bottom face of the first portion over the convex layer is positioned higher than the bottom face of the second portion. Also, the convex layer is formed from the same resin material as the inter-layer insulation layer. As such, during the formation of the convex layer, the material, equipment, technology, and so on used in forming the inter-layer insulation layer may be re-used, enabling any decrease in manufacturing efficiency caused by the addition of the convex layer to be constrained.

The organic electroluminescence display panel manufacturing method pertaining to one aspect of the present disclosure may further include, before forming the first lower electrode and the second lower electrode: applying a resin material over the substrate so that a shape of a top face of a film of the applied resin material is in conformity with a shape of the top face of the substrate; and forming an inter-layer insulating layer by reducing a thickness of a part of the film with a photolithography method using a half-tone mask, the inter-layer insulating layer including a planar portion whose top face has a shape in conformity with the shape of the top surface of the substrate and a convex portion protruding upward with respect to the planar portion, and the first lower electrode and the second lower electrode may be formed over the planar portion at opposite sides of the convex portion in the first direction and each with smaller thickness than the convex portion, such that at least a part of the bottom face of the first portion is positioned higher than the bottom face of the second portion.

The organic electroluminescence display panel manufacturing method pertaining to one aspect of the present disclosure may further include, before forming the first lower electrode and the second lower electrode: applying a resin material over the substrate so that a shape of a top face of a film of the applied resin material is in conformity with a shape of the top face of the substrate; and forming an inter-layer insulating layer by reducing a thickness of a part of the film with a photolithography method using dry etching, the inter-layer insulating layer including a planar

portion whose top face has a shape in conformity with the shape of the top surface of the substrate and a convex portion protruding upward with respect to the planar portion, and the first lower electrode and the second lower electrode may be formed over the planar portion at opposite sides of the convex portion in the first direction and each with smaller thickness than the convex portion, such that at least a part of the bottom face of the first portion is positioned higher than the bottom face of the second portion.

Accordingly, at least a part of the bottom face of the first portion over the convex layer is positioned higher than the bottom face of the second portion. Also, the convex layer is formed in the same process as the inter-layer insulation layer. Thus, during the formation of the convex layer, the material, equipment, technology, and so on used in forming the inter-layer insulation layer may be re-used, enabling any decrease in manufacturing efficiency caused by the addition of the convex layer to be constrained.

In the organic electroluminescence display panel manufacturing method pertaining to one aspect of the present disclosure, the first lower electrode and the second lower electrode may be formed such that, in a second direction that is along the top face of the substrate and that is perpendicular to the first direction, the first lower electrode is formed in plurality to form a line of first lower electrodes, and the second lower electrode is formed in plurality of form a line of second lower electrodes, the first organic light-emitting layer may be formed to extend in the second direction over the line of first lower electrodes, and the second organic light-emitting layer may be formed to extend in the second direction over the line of second lower electrodes, and the partition wall may be formed to extend in the second direction over the gap, and so that in any cross-section taken along the second direction, at least a part of the bottom face of the first portion is positioned higher than the bottom face of the second portion.

The organic electroluminescence display panel manufacturing method pertaining to one aspect of the present disclosure may further include, before forming the first lower electrodes and the second lower electrodes, forming a convex layer by using an electrically insulating material, the convex layer formed over the substrate to extend in the second direction, and the first lower electrodes and the second lower electrodes may be formed at opposite sides of the convex layer in the first direction with smaller thickness than the convex layer, and in any cross-section of the partition wall taken along the second direction, at least a part of the bottom face of the first portion may be positioned higher than the bottom face of the second portion.

Accordingly, sinking of the top face of the partition wall over the first portion is constrained along the second direction during formation of the partition wall, and ink running is unlikely to occur in the second direction during formation of the organic light-emitting layers. As such, the quality of the manufactured organic electroluminescence display panel is further stabilized.

The organic electroluminescence display panel manufacturing method pertaining to one aspect of the present disclosure may further include, before forming the partition wall: applying a resin material along the top face of the substrate having the line of first lower electrodes and the line of second lower electrodes formed thereon, so that a film of the applied resin material has greater thickness than the first lower electrodes and the second lower electrodes; and forming a convex layer and a pixel insulation layer by removing parts of the film over the first lower electrodes and the second lower electrodes with a photolithography method

using a half-tone mask and thereby reducing the thickness of the film at the parts, the convex layer formed to have greater thickness than the first lower electrodes and the second lower electrodes and to extend in the second direction between the line of the first lower electrodes and the line of the second lower electrodes, the pixel insulation layer formed to have greater thickness than the first lower electrodes and the second lower electrodes and smaller thickness than the convex layer and to extend in the first direction between electrodes adjacent in the second direction, the electrodes adjacent in the second direction comprising a combination of two first lower electrodes and a combination of two second lower electrodes, and in any cross-section of the partition wall taken along the second direction, at least a part of the bottom face of the first portion may be positioned higher than the bottom face of the second portion.

Accordingly, forming the pixel insulation layer enables improvements to the electrical insulation between neighboring pairs of the first lower electrodes and second lower electrodes, constrains tier cutting of the first organic light-emitting layer and the second organic light-emitting layer, and enables improvements to the electrical insulation between the first lower electrodes, the second lower electrodes, and the upper electrode. Also, in the above-described manufacturing method, the convex layer and the pixel insulation layer may be formed simultaneously, enabling any decrease in manufacturing efficiency caused by the addition of the convex layer to be constrained.

In the present document, the term “over” indicates not only an upper direction (vertically above) in an absolute spatial sense, but also includes relative positional relationships defined in terms of lamination order in the laminated structure of the organic electroluminescence display panel. Specifically, in the organic electroluminescence display panel, an upward direction is defined as a direction oriented perpendicularly to a main surface of a substrate toward laminated components, beginning from the substrate. Also, for example, the wording “over the substrate” does not only designate a region in direct contact with the substrate, but also includes a region above the substrate across from laminated components. Also, for example, the wording “above the substrate” does not only designate a region above the substrate with spacing therebetween but also includes a region over the substrate.

(Embodiment)

An organic electroluminescence display panel pertaining to an embodiment of the present disclosure is described below, with reference to the accompanying drawings. Here, the drawings include schematic representations. The components may differ from reality in being reduced in size, having different aspect ratios, and so on.

1. Overall Configuration of Organic Electroluminescence Display Device 1

FIG. 1 is a block diagram illustrating the overall configuration of an organic electroluminescence display device 1. The organic electroluminescence display device 1 is a display device used, for example, in a television, a personal computer, a mobile terminal, an industrial display (electronic signage, large screens for commercial use), or the like. The organic electroluminescence display device 1 is equipped with an organic electroluminescence display panel 10 and a drive control unit 20 electrically connected thereto.

The organic electroluminescence display panel 10 (hereinafter also termed a panel 10) is, for example, a top emission display panel in which a top face is a rectangular image display face. On the panel 10, a plurality of (non-diagrammed) organic electroluminescence elements are

arranged along the image display face. An image is displayed by a combination of emitted light from the organic electroluminescence elements. Also, the panel 10 employs an active matrix method, for example.

The drive control unit 20 includes a drive circuit 21 connected to the panel 10, and a control circuit 22 connected to one of an external device such as a calculator, and a receiver device such as an antenna, or the like. The drive circuit 21 includes a power supply circuit supplying electric power to the organic electroluminescence elements, a signal circuit applying a voltage signal controlling the electric power supplied to the organic electroluminescence elements, a scanning circuit switching a location of application for the voltage signal at a fixed interval, and so on. The control circuit 22 controls operations of the drive circuit 21 in accordance with data in image information input from the external device and the receiver device.

In FIG. 1, the drive circuit 21 is disposed in plurality at four locations surrounding the panel 10, as an example. However, no such limitation is intended to the configuration of the drive control unit 20. The quantity and position of the drive circuits 21 may be adjusted as appropriate. In addition, for the following explanations, and as indicated in FIG. 1, the direction along a long edge of the top face of the panel 10 is the X direction, and the direction along a short edge of the top face of the panel 10 is the Y direction.

2. Panel 10 Configuration

(1) Planar Configuration

FIG. 2 is a schematic plan view of a magnified portion of the image display face of the panel 10. Sub-pixels 100R, 100G, and 100B are arranged in a matrix on the panel 10, for example, and respectively emit light in red, green, and blue. The sub-pixels 100R, 100G, and 100B are aligned in alternation along the X direction. A group of the sub-pixels 100R, 100G, and 100B aligned in the X direction configures a single pixel P. The pixel P is capable of full color representation by combining emitted light brightness of the sub-pixels 100R, 100G, and 100B, subject to tone control.

In addition, each line in the Y direction is composed of only sub-pixels (the sub-pixels 100R, the sub-pixels 100G, or the sub-pixels 100B) of the same color, thus forming a sub-pixel column CR, a sub-pixel column CG, and a sub-pixel column CB. As a result, on the panel 10 as a whole, pixels P are arranged in a matrix along the X direction and the Y direction. The image is displayed on the image display face by combining the emitted colors of the pixels P arranged in this matrix.

Organic electroluminescence elements respectively emitting red, green, and blue light are disposed in the sub-pixels 100R, 100G, and 100B. The light emitted by the sub-pixels 100R, 100G, and 100B may have the color of emitted light of the organic electroluminescence elements themselves. Also, the color of the light emitted by the organic electroluminescence elements may be corrected by a color filter.

The panel 10 employs a line bank scheme, for example. That is, a partition wall 105 shaped to partition each of the sub-pixel columns CR, CG, and CB is formed in plurality with spacing in the X direction. In the sub-pixel columns CR, CG, and CB, the sub-pixels 100R, 100G, and 100B share an organic light-emitting layer. However, a pixel insulation layer 104 insulating adjacent sub-pixels of the same color (adjacent sub-pixels 100R, adjacent sub-pixels 100G, and adjacent sub-pixels 100B) from each other is disposed in plurality with spacing in the Y direction. This enables each of the sub-pixels of the same color (each of the sub-pixels 100R, each of the sub-pixels 100G, and each of

the sub-pixels **100B**) to emit light independently. FIG. 2 illustrates the pixel insulation layers **104** and the partition walls **105** in dotted lines. This signifies that the pixel insulation layers **104** and the partition walls **105** are not exposed on the surface of the image display face, being instead arranged inside the image display face.

(2) Cross-Sectional Configuration

FIG. 3A is a schematic cross-sectional diagram taken along line 3A-3A of FIG. 2. FIG. 3B is a schematic cross-sectional diagram taken along line 3B-3B of FIG. 2. FIG. 3A is centered on the cross-sectional configuration of sub-pixel **100G** and sub-pixel **100B**. FIG. 3B illustrates the cross-sectional configuration of sub-pixel column CB. Note that the sub-pixel **100R** also has a configuration similar to those illustrated in FIG. 3A, and the sub-pixel columns CR and CG also have a configuration similar to that illustrated in FIG. 3B. Also, in FIGS. 3A and 3B, the top of the page is oriented in the Z direction.

The panel **10** is equipped with a substrate **101**, a first lower electrode **111** and a second lower electrode **121** disposed on the top face of the substrate **101** with a gap G therebetween in the X direction, and the partition wall **105** separating the space above the first lower electrode **111** from the space above the second lower electrode **121**. Accordingly, the X direction corresponds to a first direction of the present embodiment. The term first direction X is also used below. In addition, the panel **10** is equipped with a first organic light-emitting layer **113** and a second organic light-emitting layer **123** which are respectively arranged on the top of the first lower electrode **111** and on the top of the second lower electrode **121** and are partitioned by the partition wall **105**. Further, the panel **10** is equipped with an upper electrode **107** is arranged above the first organic light-emitting layer **113** and the top of the second organic light-emitting layer **123**.

Here, as illustrated in FIG. 4, which is a magnification of the double-chained portion of FIG. 3A, the partition wall **105** includes a first portion **105F** above the gap G, and second portions **105S** neighboring the first portion **105F** on both sides in the first direction X, disposed over the first lower electrode **111** and over the second lower electrode **121**. The dashed lines in FIG. 3A and FIG. 4 represent the boundaries of the first portion **105F** and the second portions **105S**. Furthermore, in the panel **10**, at least part of a bottom face **105FB** of the first portion **105F** is positioned higher than bottom faces **105SB** of the second portions **105S**.

In addition, the panel **10** is also equipped with an inter-layer insulation layer **102** disposed over the substrate **101** and having a top face shaped in conformity with the top face of the substrate **101**. Further, the panel **10** is equipped with a convex layer **103** having greater thickness than the first lower electrode **111** and the second lower electrode **121** and provided between the inter-layer insulation layer **102** and the first portion **105F**. The first lower electrode **111**, the second lower electrode **121**, and the convex layer **103** are disposed over the inter-layer insulation layer **102**. In addition, the panel **10** is equipped with a first hole transport layer **112** and a second hole transport layer **122** respectively disposed between the first lower electrode **111** and the first organic light-emitting layer **113**, and between the second lower electrode **121** and the second organic light-emitting layer **123**. Further, the panel **10** is equipped with an electron transport layer **106** disposed between the upper electrode **107** and the pair of the first organic light-emitting layer **113** and the second organic light-emitting layer **123**, and a thin film sealing layer **108** arranged over the upper electrode **107**. Also, as illustrated in FIG. 2 and FIG. 3B, the panel **10** is

equipped with the pixel insulation layer **104** shaped to extend along the first direction X, between pairs of the first lower electrode **111** and between pairs of the second lower electrode **121**.

In the above description, the numbers first and second applied to the lower electrodes, the hole transport layers, and the organic light-emitting layers are used for convenience, in order to distinguish between neighboring electrodes and layers in the first direction X. Accordingly, the terms first and second do not correspond one-to-one to pairs of the sub-pixels **100G** and **100B**. The first components may correspond to the sub-pixels **100R** and **100B**, and the second components may correspond to the sub-pixels **100R** and **100G**. Also, in the following description, the terms lower electrodes **111**, **121**, hole transport layers **112**, **122**, and organic light-emitting layers **113**, **123** are also used in situations where there is no need to distinguish between the first and second components.

(3) Description of Components

a. Substrate **101**

The substrate **101** is a flat, rectangular plate and serves as a support member supporting the panel **10**. Here, a thin film transistor (hereinafter, TFT) layer is formed over the substrate **101**, but is not illustrated in the drawings.

An electrically insulating material is used in the substrate **101**, for example. Specific examples of such a material include glass materials such as non-alkali glass, soda glass, non-fluorescent glass, phosphate glass, borate glass, quartz glass, and so on, resin materials such as acrylic resin, styrene resin, polycarbonate resin, epoxy resin, polyethylene resin, polyester resin, polyimide resin, silicone resin, and so on, and metal oxide materials such as aluminum oxide. The substrate **101** may also have a multilayer structure in which a layer of electrically insulating material is laminated over a layer of metal material such as aluminum, stainless steel, and so on.

Given that organic electroluminescence elements typically degrade upon reacting with water, oxygen, and so on, the substrate **101** beneficially has low permeability to water. As such, a glass material, a metal material, and so on are beneficially used. Also, in a situation where a resin material is used for the substrate **101**, a multilayer structure is beneficially used such that a layer having low permeability to water, such as silicon nitride, silicon oxide, aluminum oxide, and the like, is layered over the resin material.

An electronic circuit controlling electric power supply to the organic electroluminescence element is disposed in the TFT layer. The TFT layer includes laminated layers, namely a semiconductor layer, a conductive layer, an electrically insulating layer, and so on, as well as electronic circuit elements such as a TFT element, a condenser element, wiring, and the like. In addition, a topmost portion of the TFT layer is made from a material that is electrically insulating and has low permeability to water, such as silicon nitride, aluminum oxide, or the like. A passivation layer may also be disposed thereon so as to entirely cover the electronic circuit elements of the TFT layer.

b. Inter-Layer Insulation Layer **102**

The inter-layer insulation layer **102** is made from a resin material, is disposed over the substrate **101**, which includes the TFT layer, and serves to electrically insulate the electronic circuit elements of the TFT layer, the organic electroluminescence elements, and so on. In addition, the inter-layer insulation layer **102** also serves to fill irregularities on the substrate **101** caused by the TFT layer. The top face of the inter-layer insulation layer **102** is planarized in conformity with the top face of the substrate **101**.

Specific examples of the resin material used for the inter-layer insulation layer **102** include acrylic resin, polyimide resin, silicone resin, phenolic resin, and other electrically insulating materials susceptible to patterning.

c. Convex Layer **103**

The convex layer **103** is a layer substantially shaped as a truncated square pyramid, disposed over the inter-layer insulation layer **102**. The material used for the convex layer **103** is, for example, an electrically insulating material. Specific examples of such a material include the resin materials listed for the inter-layer insulation layer **102**, as well as inorganic materials such as silicon nitride, silicon oxide, silicon oxinitride, aluminum oxide, and so on. The inter-layer insulation layer **102** and the convex layer **103** are beneficially formed from the same resin material, as described later.

Here, the thickness of the convex layer **103** is greater than the respective thicknesses of the first lower electrode **111** and the second lower electrode **121**. Due to this difference in thickness, the foundation of the partition wall **105**, made up of the first lower electrode **111**, the second lower electrode **121**, and the convex layer **103**, is shaped such that a part of the foundation below the first portion **105F** protrudes upward with respect to parts of the foundation below the second portions **105S**. As a result, in the panel **10**, at least part of the bottom face **105FB** is raised above the bottom faces **105SB**.

Also, as illustrated in FIG. **5**, which is a schematic perspective view diagram illustrating a state prior to formation of the partition wall **105**, the convex layer **103** is shaped so as to extend in the Y direction, which intersects the first direction X along the top face of the substrate **101**. Here, the Y direction corresponds to a second direction of the present embodiment. The term second direction Y is also used below. The convex layer **103** is shaped so as to extend along the above-described Y direction. As such, in the panel **10**, a part of the foundation below the first portion **105F** protrudes upward with respect to parts of the foundation below the second portions **105S** at any area along the second direction Y. As a result, in the panel **10**, at least part of the bottom face **105FB** is higher than the bottom faces **105SB**, in any lateral cross-section of the partition wall **105** taken along the second direction Y. Here, given a shape extending in one direction, the lateral cross-section refers to a cross-section taken perpendicularly with respect to the direction of extension.

d. Pixel Insulation Layer **104**

The pixel insulation layer **104** is made from an electrically insulating material. As illustrated in FIG. **3B**, the pixel insulation layer **104** covers end portions of neighboring electrodes (neighboring first lower electrodes **111** or neighboring the second lower electrodes **121**) within each of the sub-pixel columns CR, CG, and CB, and is shaped so as to partition the neighboring electrodes from one another. Specifically, as illustrated in FIG. **5**, the pixel insulation layer **104** is shaped so as to extend along the first direction X between neighboring electrodes (neighboring first lower electrodes **111** and neighboring the second lower electrodes **121**). In addition, the thickness of the pixel insulation layer **104** is greater than the thickness of the first lower electrode **111** and the second lower electrode **121**, and less than the thickness of the convex layer **103**. Accordingly, the hole transport layers **112**, **122** and the organic light-emitting layers **113**, **123** in the sub-pixel columns CR, CG, and CB are not partitioned by the pixel insulation layer **104**, which is thinner than the partition wall **105**, and the flow of ink

during formation of the hole transport layers **112**, **122** and the organic light-emitting layers **113**, **123** is not obstructed.

According to the above-described configuration, the pixel insulation layer **104** serves to constrain tier cutting in the hole transport layers **112**, **122** and the organic light-emitting layers **112**, **123** in the sub-pixel columns CR, CG, and CB while improving the electrical insulation between neighboring electrodes (neighboring first lower electrodes **111** and neighboring the second lower electrodes **121**), to improve the electrical insulation between the lower electrodes **111**, **121** and the upper electrode **107**, and so on.

Specific examples of the electrically insulating material used for the pixel insulation layer **104** include the resin materials and inorganic materials listed for the convex layer **103**. Also, in order to facilitate the flow and spread of ink during formation of the hole transport layers **112**, **122**, the surface of the pixel insulation layer **104** is beneficially lyophilic with respect to ink.

e. First Lower Electrode **111** and Second Lower Electrode **121**

The lower electrodes **111**, **121** are arranged over the substrate **101** in a matrix made up of the first direction X and the second direction Y, and serve as anodes supplying holes to the organic light-emitting layers **113**, **123**, respectively. Specifically, the lower electrodes **111**, **121** are flat, rectangular members disposed over the inter-layer insulation layer **102** and neighboring both sides of the convex layer **103** in the first direction X. Also, the lower electrodes **111**, **121** define the positions of the organic electroluminescence elements, and are in one-to-one correspondence with the sub-pixels **100R**, **100G**, and **100B**. As illustrated in FIG. **5**, in the panel **10**, the first lower electrode **111** and the second lower electrode **121** are each provided in plurality. The plurality of the first lower electrodes **111** are aligned in the second Y direction, thus forming a first lower electrode column **111C**. Similarly, the plurality of the second lower electrodes **121** are aligned in the second Y direction, thus forming a second lower electrodes column **121C**. In situations where there is no particular need to distinguish between the first lower electrode column **111C** and the second lower electrode column **121C**, the term lower electrode columns **111C**, **121C** is used below.

Each of the lower electrodes **111**, **121** has a two-layer configuration of different materials. Specifically, the lower electrode **111** is composed of a first metal layer **111a** made of a metal material on a lower side, and a first oxide layer **111b** made of a metal oxide material on an upper side. Similarly, the lower electrode **121** is composed of a second metal layer **121a** made of a metal material on a lower side, and a second oxide layer **121b** made of a metal oxide material on an upper side.

Specific examples of the metal material used for the first metal layer **111a** and the second metal layer **121a** include aluminum (Al), silver (Ag), molybdenum (Mo), tungsten (W), titanium (Ti), chromium (Cr), nickel (Ni), zinc (Zn), copper (Cu), gold (Au), platinum (Pt), palladium (Pd), and so on. The metal material may also be a metal alloy combining a plurality of metal materials, and may be a layered material combining a metal and a metal alloy.

For considerations of hole supply, a material having a high work function is beneficially used for the first metal layer **111a** and the second metal layer **121a**. Also, given that the panel **10** is a top emission panel, the first metal layer **111a** and the second metal layer **121a** are beneficially optically reflective.

Specific examples of metal oxide materials used for the first oxide layer **111b** and the second oxide layer **121b**

include oxides of Ag, Mo, Cr, W, Ni, vanadium (V), iridium (Ir), and so on. The presence of the first oxide layer **111b** and the second oxide layer **121b** serves to lower the energy barrier for hole supply (i.e., hole injection) from the lower electrodes **111**, **121** to the organic light-emitting layers **113**, **123**, respectively, and to improve the efficiency of hole injection. That is, the first oxide layer **111b** and the second oxide layer **121b** serve as hole injection layers.

However, the lower electrodes **111**, **121** are not limited to the above-described configuration. For example, the lower electrodes **111**, **121** may respectively include only the first metal layer **111a** and the second metal layer **121a**, and may further include additional layers having different functions. For instance, a layer of transparent, conductive oxide material, such as indium tin oxide (ITO), indium zinc oxide (IZO), and so on, may be disposed between the first metal layer **111a** and the first oxide layer **111b** and between the second metal layer **121a** and the second oxide layer **121b** in order to improve adhesion and prevent oxidation of the metal material. Also, for example, a barrier metal layer made from a metal oxide material, such as tungsten oxide, may be disposed below the first metal layer **111a** and the second metal layer **121a** in order to constrain corrosion during wet etching and to constrain the dispersion of hydrogen to the lower layers.

In addition, a layer of conductive oxide material, such as ITO and IZO, and a layer of conductive carbon material, such as graphite, carbon nanotube, and so on, may be disposed instead of each of the first metal layer **111a** and the second metal layer **121a**.

f. First Hole Transport Layer **112** and Second Hole Transport Layer **122**

The hole transport layers **112**, **122** are respectively disposed over the lower electrodes **111**, **121**, and serve to improve the transport of the holes supplied by the lower electrodes **111**, **121** to the organic light-emitting layers **113**, **123**, respectively. In addition, the hole transport layers **112**, **122** are formed in using a wet process in regions partitioned by the partition wall **105**. As illustrated in FIG. 3B, each hole transport layers **112**, **122** are shaped so as to extend along the second direction Y above the lower electrode columns **111C**, **121C** and over the pixel insulation layer **104**. As a result, sub-pixels (sub-pixels **100R**, sub-pixels **100G**, or sub-pixels **100B**) in each sub-pixel column (sub-pixel column CR, sub-pixel column CG, and sub-pixel column CB) share the same hole transport layer (hole transport layer **112** or hole transport layer **122**). Also, for considerations of light-emission efficacy, drive voltage optimization, and so on, the hole transport layers **112**, **122** may have thicknesses that vary among the sub-pixel columns CR, CG, and CB.

An organic material having high hole mobility is used, for example, as the material for the hole transport layers **112**, **122**. Specific examples of such a material include triazole derivative, oxadiazole derivative, imidazole derivative, pol-yarylalkane derivative, pyrazoline derivative, pyrazolone derivative, phenylenediamine derivative, arylamine derivative, amino-substituted chalcone derivative, oxazole derivative, styrylanthracene derivative, fluorenone derivative, hydrazone derivative, stilbene derivative, porphyrin compound, aromatic tertiary amine compound, styrylamine compound, butadiene compound, polystyrene derivative, triphenylmethane derivative, and tetraphenylbenzene derivative (all disclosed in Japanese Patent Application Publication No. H5-163488). In addition, the hole transport layers **112**, **122** may be compound layers combining the above-described materials and other materials. Also, for considerations of light-emission efficacy, drive voltage opti-

mization, and so on, the hole transport layers **112**, **122** may use different materials among the sub-pixel columns CR, CG, and CB.

g. First Organic Light-Emitting Layer **113** and Second Organic Light-Emitting Layer **123**

The organic light-emitting layers **113**, **123** include an organic light-emitting material and are respectively disposed over the hole transport layers **112**, **122**. Light emission (i.e., electroluminescence) occurs through the recombination of electrons with the holes supply by the lower electrodes **111**, **121** and the upper electrode **107** in the organic light-emitting layers **113**, **123**. In addition, the organic light-emitting layers **113**, **123** are formed in using a wet process in regions partitioned by the partition wall **105**. As illustrated in FIG. 3B, the organic light-emitting layers **113**, **123** are shaped so as to extend along the second direction Y above the first lower electrode column **111C** and the second lower electrode column **121C**. As a result, sub-pixels (sub-pixels **100R**, sub-pixels **100G**, or sub-pixels **100B**) in each sub-pixel column (sub-pixel column CR, sub-pixel column CG, and sub-pixel column CB) share the same organic light-emitting layer (organic light-emitting layer **113** or organic light-emitting layer **123**). However, the organic light-emitting layers **113**, **123** are also capable of independent light emission in each portion above the lower electrodes **111**, **121**, that is, in each of the sub-pixels **100R**, **100G**, and **100B**. Also, for considerations of light-emission efficacy, drive voltage optimization, and so on, the organic light-emitting layers **113**, **123** may have thicknesses that vary among the sub-pixel columns CR, CG, and CB.

The organic light-emitting material in the organic light-emitting layers **113**, **123** may be one of a low-molecular material and a high-molecular material. Specific examples of the organic light-emitting material include fluorescent materials and phosphorous materials, such as an oxinoid compound, perylene compound, coumarin compound, azacoumarin compound, oxazole compound, oxadiazole compound, perinone compound, pyrrolo-pyrrole compound, naphthalene compound, anthracene compound, fluorene compound, fluoranthene compound, tetracene compound, pyrene compound, coronene compound, quinolone compound, azaquinolone compound, pyrazoline derivative, pyrazolone derivative, rhodamine compound, chrysene compound, phenanthrene compound, cyclopentadiene compound, stilbene compound, diphenylquinone compound, styryl compound, butadiene compound, dicyanomethylene pyran compound, dicyanomethylene thiopyran compound, fluorescein compound, pyrylium compound, thiapyrylium compound, selenapyrylium compound, telluropirylium compound, aromatic aldadiene compound, oligophenylene compound, thioxanthene compound, cyanine compound, acridine compound, metal complex of a 8-hydroxyquinoline compound, metal complex of a 2-bipyridine compound, complex of a Schiff base and a group three metal, metal complex of oxine, and rare earth metal complex (all disclosed in Japanese Patent Application Publication No. H5-163488).

The organic light-emitting layers **113**, **123** may also be compound layers combining the organic light-emitting material and another material. Here, a three-color divided application scheme is used for the panel **10**, in which the organic light-emitting layers **113**, **123** include an organic light-emitting material respectively emitting red, green, and blue light for each of the sub-pixel columns CR, CG, and CB. Accordingly, the first organic light-emitting layer **113**

and the second organic light-emitting layer **123** neighboring each other in the first direction X emit light of different colors.

h. Partition Wall **105**

The partition wall **105** is a wall-shaped member having the lower electrodes **111**, **121** and the convex layer **103** as foundation layers, and disposed in correspondence with each gap G (convex layer **103**). The partition wall **105** is shaped as a partition between the first hole transport layer **112** and the second hole transport layer **112**, and between the first organic light-emitting layer **113** and the second organic light-emitting layer **123**, all of which being formed by the wet process. The partition wall **105** serves to constrain ink running in the first direction X during the manufacturing process. The partition wall **105** also serves to electrically insulate neighboring hole transport layers **112**, **122** and neighboring organic light-emitting layers **113**, **123** in the first direction X from one another.

Furthermore, the partition wall **105** is shaped so as to extend in the second direction Y between neighboring subpixel columns CR, CG, and CB in the first direction X as illustrated in FIG. 2, and more specifically between the first organic light-emitting layer **113** and the second organic light-emitting layer **123** as illustrated in FIG. 3A. That is, the partition wall **105** has a line bank shape.

An electrically insulating material is used for the partition wall **105**. Specific example of the electrically insulating material include the resin materials and inorganic materials listed for the convex layer **103**. When using a resin material, a photosensitive material is beneficial for considerations of workability. The photosensitive material may be one of positive and negative, the latter being beneficial. The partition wall **105** may also be a compound layer combining the above-described electrically insulating material and another material, and may be have a multi-layer structure combining layers of the above-listed materials.

The partition wall **105** is beneficially resistant to organic solvents and to heat. Also, in order to constrain ink running, a surface of the partition wall **105** is beneficially liquid-repellent. For example, one of using a liquid-repellent material for the partition wall **105** and applying a surface process to make the partition wall **105** liquid repellent is beneficially employed.

As described above, in the panel **10**, at least a part of the bottom face **105FB** is positioned higher than the bottom faces **105SB**. As a result, in the panel **10**, sinking of the top face **105T** of the first portion **105F** of the partition wall **105** is constrained during the formation of the partition wall **105**. Accordingly, the panel **10** has a structure in which ink is unlikely to run during the formation of the first organic light-emitting layer **113** and the second organic light-emitting layer **123**, which makes for stable product quality.

Also, in the panel **10**, at least a part of the bottom face **105FB** is positioned higher than the bottom faces **105SB**, in any lateral cross-section of the partition wall **105** along the second direction Y. As a result, sinking of the top face **105T** of the first portion **105F** of the partition wall **105** is constrained during the formation of the partition wall **105**. Accordingly, the panel **10** has a structure along the second direction Y in which ink is unlikely to run during the formation of the first organic light-emitting layer **113** and the second organic light-emitting layer **123**, which makes for more stable product quality.

i. Electron Transport Layer **106**

The electron transport layer **106** is disposed over the organic light-emitting layers **113**, **123**. The electron transport layer **106** serves to improve the transport of the elec-

trons supplied by the upper electrode **107** to the organic light-emitting layers **113**, **123**. As illustrated in FIGS. 3A and 3B, the electron transport layer **106** is also disposed over the partition wall **105**, so as to be a continuous layer shared by the sub-pixels **100R**, **100G**, and **100B**.

An organic material having high electron mobility, for example, is used for the electron transport layer **106**. Specific examples of such a material include nitro-substituted fluorenone derivative, thiopyran dioxide derivative, diphenylquinone derivative, perylene tetracarboxyl derivative, anthraquinodimethane derivative, fluoronylidene methane derivative, anthrone derivative, oxadiazole derivative, perinone derivative, and quinolone complex derivative (all disclosed in Japanese Patent Application Publication No. H5-163488), as well as phosphorous oxide derivative, triazole derivative, triazine derivative, silole derivative, dimethyl boron derivative, and triaryl boron derivative. In addition, the electron transport layer **106** may be a compound layer combining the above-described materials and other materials.

j. Upper Electrode **107**

The upper electrode **107** is disposed over the organic light-emitting layers **113**, **123**, specifically so as to cover the electron transport layer **106**, and serves as a cathode supplying electrons to the organic light-emitting layers **113**, **123**.

A conductive material is, for example, used for the upper electrode **107**. Specific examples of such a material include the materials listed for the lower electrodes **111**, **121**. For electron supply considerations, a material having a low work function is beneficially used for the upper electrode **107**. In addition, the upper electrode **107** beneficially has high optical transmittance given that the panel **10** is a top emission panel. Also, imparting optical reflectivity to the lower electrodes **111**, **121** as well as the upper electrode **107** and forming a resonator structure enables improved wavelength selectivity for emitted light and improvements to color purity for the light emitted by the sub-pixel **100R**, **100G**, **100B**.

k. Thin Film Sealing Layer **108**

The thin film sealing layer **108** entirely covers the top face of the substrate **101** (inter-layer insulation layer **102**) on which the above-described components are arranged, and serves to protect the components from physical shocks, atmospheric water, oxygen, and so on. A material having low permeability to water, for example, is used for the thin film sealing layer **108**. Specific examples of such a material include inorganic materials such as silicon nitride, silicon oxide, carbon oxide, carbon nitride, aluminum oxide, and so on. Also, given that the panel **10** is a top emission panel, a material having high optical transmittance and a small difference in refractive index relative to the upper electrode **107** is beneficially used for the thin film sealing layer **108**.

3. Manufacturing Method of Panel **10**

(1) Overall Process

An overall process concerning a manufacturing method for the panel **10**, which is an embodiment of the disclosure, is described below. FIGS. 6A to 6C, 7A to 7C, and 8A to 8C are schematic cross-sectional diagrams illustrating the manufacturing method of the panel **10**. The cross-sections illustrated in FIGS. 6A to 6C, 7A to 7C, and 8A to 8C correspond to the cross-section illustrated in FIG. 3A.

a. Substrate Preparation

First, the substrate **101** is prepared. Specifically, an electrically insulating material is shaped into a flat plate and used

as the substrate **101**. In addition, the TFT layer and the passivation layer, where necessary, are formed on the substrate **101** at this time.

Specifically, for example, a layer of semiconductor material and a layer of one of an electrically conducting material and an electrically insulating material are first formed over the substrate **101**. The formation method used for these layers may be, for example, a dry process such as vacuum deposition, electron beam deposition, ion plating, sputtering, and vapor phase epitaxy, and a wet process such as printing, spin coating, inkjet, dispensing, die coating, and slit coating, in accordance with the material of each layer.

Here, patterning may be performed as needed, such that the above-described layers have a predetermined shape. The patterning method may involve, for example, arranging a metal mask or a print mask to cover unnecessary portions during layer formation and forming the above-described layers only at necessary positions. Also, the patterning method may be a combination of dry etching and wet etching, a photolithography method, or the like, performed in order to remove unnecessary portions after the above-described layers have been formed.

In addition, plasma injection, ion injection, baking, and other processes may be performed on the formed layers as needed.

The TFT layer may be formed through repeated formation of the above-described layers to form a laminated structure configuring predetermined electronic circuits. Furthermore, the passivation layer may be formed so as to cover the substrate **101** on which the TFT layer is formed, as necessary. The above-described examples of wet processes and dry processes may be used to form the passivation layer, in accordance with the materials. Also, the above-described examples of patterning method may be used in a situation where openings (contact holes) are formed at predetermined positions in the passivation layer in order to electrically connect TFT elements of the TFT layer and the lower electrodes **111**, **121**.

b. Inter-Layer Insulation Layer Formation

Next, as illustrated in FIG. 6A, a resin material is used to form the inter-layer insulation layer **102** over the substrate **101**, with a top face having a shape that conforms to the top face of the substrate **101**. Specifically, a resin material having a fixed fluidity is applied along the top face of the substrate **101** using, for example, die coating, so as to fill irregularities on the substrate **101** caused by the (non-diagrammed) TFT layer. As a result, the top face of the inter-layer insulation layer **102** is planarized along the top face of the substrate **101**. Also, the above-described examples of the patterning method may be used in a situation where openings (contact holes) are formed at predetermined positions in the inter-layer insulation layer **102**, similarly to the passivation layer.

c. Convex Layer Formation

Next, as illustrated in FIG. 6B, an electrically insulating material is used to form the convex layer **103** over the inter-layer insulation layer **102**, in a shape extending in the second direction Y. The specific formation method is described later.

d. Lower Electrode Formation

Next, as illustrated in FIG. 6C, the first lower electrode **111** and the second lower electrode **121** are formed over the substrate **101**, arranged on the top face of the substrate **101** with the gap G therebetween in the first direction. This involves forming the first lower electrode **111** and the second lower electrode **121** over the inter-layer insulation layer **102**, each at a different side of the convex layer **103** in the first

direction X. In addition, as illustrated in FIG. 5, the formation of the lower electrodes **111**, **121** involves forming the first lower electrode **111** and the second lower electrode **121** in plurality along the second direction Y, thus forming the first lower electrode column **111C** and the second lower electrode column **121C**.

Specifically, for example, a metallic thin film is first formed over the inter-layer insulation layer **102** and over the convex layer **103**, from the material of the first metal layer **111a** and the second metal layer **121a** using a sputtering method. Afterward, a thin film of metal oxide material is formed over the metallic thin film from the material of the first oxide layer **111b** and the second oxide layer **121b**, using a reactive sputtering method. Here, film formation conditions are adjusted such that the total thickness of the metallic thin film and the metal oxide film is less than the thickness of the convex layer **103**. Next, a photoresist material is applied to the top of the metal oxide film and patterning is subsequently performed using photolithography on the photoresist material. This photoresist material remains over the film of metallic oxide in portions corresponding to the sub-pixels **100R**, **100G**, and **100B** at both sides of the convex layer **103** in the first direction X. A dry etching method and a wet etching method are then used in the stated order to perform continuous etching of the metallic thin film and the film of metal oxide where the photoresist material is not disposed. Finally, washing is performed using an appropriate washing liquid to remove the photoresist material and any dross produced by the etching and so on. According to the above, the first lower electrode **111** and the second lower electrode **121**, respectively including the first metal layer **111a** and the second metal layer **121a** laminated with the first oxide layer **111b** and the second oxide layer **121b**, are formed at predetermined positions, thus enabling the formation of the first lower electrode column **111C** and the second lower electrode column **121C**.

Here, performing continuous etching on the metallic thin film and the film of metal oxide as described above imparts efficiency to the manufacturing process. Also, using a single photoresist for patterning both films improves the formation precision for the first lower electrode **111** and the second lower electrode **121**.

Further, in a situation where a barrier metal layer is disposed below the first metal layer **111a** and the second metal layer **121a**, then in the above, the film of metal oxide is formed before the formation of the metallic thin film and dry etching of the film of metal oxide is further performed after wet etching of the metallic thin film. In addition, the formation of the lower electrodes **111**, **121** is not limited to continuous etching of the metallic thin film and the film of metal oxide. The first oxide layer **111b** and the second oxide layer **121b** may also be formed after the formation of the first metal layer **111a** and the second metal layer **121a**.

In the present manufacturing method, the first lower electrode **111** and the second lower electrode **121** are formed more thinly than the convex layer **103**. As a result, the lower electrodes **111**, **121** and the convex layer **103** having greater thickness than the lower electrodes **111**, **121** are formed prior to forming the partition wall **105**, as foundations for the partition wall **105**. That is, a part of the foundation of the partition wall **105** corresponding to the gap G protrudes upward. The respective thicknesses of the lower electrodes **111**, **121** and of the convex layer **103** may be determined as appropriate in accordance with the shape and specifications of the panel **10**. For example, in a situation where the

thickness of the lower electrodes **111**, **121** is 250 nm, the thickness of the convex layer **103** is from 500 nm to 1000 nm.

e. Pixel Insulation Layer Formation

Next, as illustrated in FIG. 7A, the pixel insulation layer **104** is formed between adjacent first lower electrodes **111** and adjacent second lower electrodes **121**, to have a shape that extends in the first direction X and a thickness that is greater than the thickness of the lower electrodes **111**, **121** and less than the thickness of the convex layer **103**. However, it should be noted that the pixel insulation layer **104** is not formed at the position illustrated by the cross-section of FIG. 7A, but rather farther along the direction of page depth, relative to the illustrated cross-section. As such, in FIG. 7A, the surface of the pixel insulation layer **104** is illustrated without hatching to represent the pixel insulation layer **104** being formed farther along the direction of page depth. The same applies to FIG. 7B.

Specifically, the formation method used for the pixel insulation layer **104** may involve, for example, using die coating to apply a resin material over the top face of the substrate **101**, on which components up to the lower electrodes **111**, **121** are formed, at a thickness that is greater than the thickness of the lower electrodes **111**, **121** and less than the thickness of the convex layer **103**. Then, the pixel insulation layer **104** may be formed using a photolithography method to apply patterning to the resin material in a shape extending in the first direction X between adjacent first lower electrodes **111** and adjacent the second lower electrodes **121**.

f. Partition Wall Formation

Next, as illustrated in FIG. 7B, the partition wall **105** is formed using an electrically insulating material, in a shape that separates the space above the first lower electrode **111** and the space above the second lower electrode **121** from one another. Here, as illustrated in FIG. 4, the partition wall **105** is formed in a shape having the first portion **105F** above the gap G, and the second portions **105S**, which neighbor the first portion **105F** on both sides in the first direction X, disposed over the first lower electrode **111** and over the second lower electrode **121**.

Specifically, the formation method for the partition wall **105** involves firstly using the die coat method to apply a resin material that includes a liquid-repellent component, such as a fluorine compound, on the top face of the substrate **101** on which components up to the pixel insulation layer **104** are formed, with a thickness that covers the top face of the convex layer **103** (i.e., the pixel insulation layer **104** over the convex layer **103**). Subsequently, a photolithography method is used to pattern the resin material into a shape extending along the second direction Y over the gap G, leaving the resin material over the gap G and over ends of neighboring pairs of the first lower electrodes **111** and the second lower electrodes **121**.

Furthermore, after patterning, the resin material may be cured using a hot air drying oven, a hot plate, an infra-red lamp, or the like to form the partition wall **105**. The curing temperature and time may be set as appropriate in accordance with the resin material, and may be, for example, from 150° C. to 250° C. and from 30 minutes to 120 minutes. Curing improves adhesion with the foundation layers, increases film density, and enables the partition wall **105** to be formed with improved strength and resistance to organic solvents. In addition, curing displaces the liquid-repellent components toward the surface of the partition wall **105** and enables the partition wall **105** to be formed with an exceptionally liquid-repellent surface. Also, curing enables any

dross remaining after development to be removed, increases top layer formation precision, and provides improvements to the quality of formation. Here, irradiating the entire top face of the substrate **101** with ultraviolet rays after curing enables the breakdown of any unnecessary liquid-repellent components and provides further top layer formation precision and improvements to the quality of formation.

In the present manufacturing method, as described above, an upwardly-protruding shape is formed in the foundation of the partition wall **105** at the positions corresponding to the gap G, prior to the formation of the partition wall **105**. As such, at least a part of the bottom face **105FB** is formed at a higher position than the bottom faces **105SB** of the second portions **105S**. As a result, in the present manufacturing method, performing curing during formation of the partition wall **105** enables sinking of the top face of the first portion **105F** of the partition wall **105** to be constrained despite any shrinking.

Here, when using an inorganic material for the partition wall **105**, a silicon oxide film may, for example, be formed using vacuum deposition or the like. In such a situation, a photolithography method, a metal mask, or the like may be used to pattern the resin material into a shape extending along the second direction Y over the gap G, leaving the resin material over the gap G and over ends of neighboring pairs of the first lower electrodes **111** and the second lower electrodes **121**, so as to form the partition wall **105**.

According to the present manufacturing method, at least a part of the bottom face **105FB** is formed at a higher position than the bottom faces **105SB** of the second portions **105S** in this situation as well. As such, sinking of the top face of the partition wall **105** on the first portion **105F** may be constrained despite the partition wall **105** being influenced by irregularities in the foundations.

g. Hole Transport Layer Formation

Next, as illustrated in FIG. 7C, the first hole transport layer **112** and the second hole transport layer **122** are respectively formed over the first lower electrode **111** and the second lower electrode **121**, partitioned by the partition wall **105**. Also, as illustrated in FIG. 3B, the hole transport layers **112**, **122** are formed so as to extend along the second direction Y over the lower electrode columns **111C**, **121C**. Specifically, the formation method for the hole transport layers **112**, **122** may be identical to that of the later-described organic light-emitting layers **113**, **123**.

h. Organic Light-Emitting Layer Formation

Next, the first organic light-emitting layer **113** and the second organic light-emitting layer **123** are respectively formed over the first lower electrode **111** and the second lower electrode **121** using a wet process, and are partitioned by the partition wall **105**. Also, at this stage, as illustrated in FIG. 3B, the first organic light-emitting layer **113** and the second organic light-emitting layer **123** are respectively formed so as to extend along the second direction Y over the first lower electrode column **111C** and the second lower electrode column **121C**.

Specifically, as illustrated in FIG. 8A, ink **113i** and ink **123i**, which include organic light-emitting materials of different light-emission colors, are first respectively applied over the first hole transport layer **112** and the second hole transport layer **122**, which are partitioned by the partition wall **105**, using an inkjet method, for example. Also, at this stage, each of the ink **113i** and the ink **123i** is applied so as to form a continuous film over the pixel insulation layer **104**, spanning over corresponding ones of the lower electrodes (first lower electrodes **111** or second lower electrodes **121**). As a result, the ink **113i** and the ink **123i** are able to flow

along the second direction Y. This enables reductions in uneven application of the ink **113i**, **123i**.

As described above, the partition wall **105** formed in the present manufacturing method is constrained from top face sinking as illustrated in FIG. 4. The ink **113i** and the ink **123i** are thus unlikely to run over the partition wall **105**. As a result, in the present manufacturing method, the formation precision of the organic light-emitting layers **113**, **123** is improved, and the quality of the panel **10** is made stable.

Subsequently, as illustrated in FIG. 8B, an organic solvent in the ink **113i**, **123i** is evaporated by heating the substrate **101**, after application of the ink **113i**, **123i**, by heating in a vacuum environment such as a vacuum chamber. Accordingly, the organic light-emitting layers **113**, **123** are formed.

i. Electron Transport Layer and Upper Electrode Formation

Next, as illustrated in FIG. 8C, the electron transport layer **106** and the upper electrode **107** are formed over the first organic light-emitting layer **113** and the second organic light-emitting layer **123**. Specifically, for example, the electron transport layer **106** and the upper electrode **107** are formed over the entirety of the substrate **101** having the components up to the organic light-emitting layers **113**, **123** formed thereon, using a dry process adapted to the materials of the electron transport layer **106** and the upper electrode **107**.

j. Thin Film Sealing Layer Formation

Lastly, as illustrated in FIGS. 3A and 3B, the thin film sealing layer **108** is formed so as to cover the top face of the substrate **101** on which the components up to the upper electrode **107** have been formed. Specifically, a thin film of an inorganic material may be formed across the top face of the substrate **101**, on which the components up to the upper electrode **107** have been formed, using a reactive sputtering method.

According to the method described above in sections a through j, the panel **10** may be manufactured to have the cross-sectional configuration illustrated in FIGS. 3A and 3B. However, the above-described method is merely an example. The formation method of each component may also employ other dry processes, patterning methods, wet processes, and so on, as appropriate.

(2) Convex Layer **103** Formation Method

The formation method of the convex layer **103** is described in detail below. FIGS. 9A, 9B, and 9C are schematic cross-sectional diagrams illustrating the formation method of the convex layer of the panel **10**.

a. Resin Material Application

First, as illustrated in FIG. 9A, a resin material **103r** is applied over the inter-layer insulation layer **102**, prior to forming the lower electrodes **111**, **121**. The specific application method may be one of the wet processes listed above, such as a sputtering method, for example. Also, after application, low-temperature heat drying (i.e., pre-baking) or the like is performed, for example, by vacuum drying at a temperature of approximately 60° C. to 120° C. in order to remove unnecessary solvents. This beneficially fixes the resin material **103r** to the inter-layer insulation layer **102**.

Here, the resin material **103r** is beneficially to the same as the resin material used for the inter-layer insulation layer **102**. As a result, during the formation of the convex layer **103**, the material, equipment, technology, and so on used for the inter-layer insulation layer **102** may be reused, which enables any decrease in manufacturing efficiency caused by the addition of the convex layer **103** to be constrained.

b. Exposure

Next, as illustrated in FIG. 9B, the resin material **103r** is exposed through a photomask PM1. Specifically, an expo-

sure device or the like is used in which the photomask PM1 is arranged over the substrate **101** having the resin material **103r** applied thereto, and the resin material **103r** is irradiated with light L0 from above the photomask PM1.

The light L0 typically includes ghi compound rays (of 436 nm, 405 nm, and 365 nm). However, g rays (436 nm), h rays (405 nm), i rays (365 nm), an excimer laser, EUV, X rays, and the like may also be used, for example. The light L0 is set in accordance with the type of the resin material **103r** and a width of the convex layer **103**. Also, the amount of the light L0 used for exposure may be set as appropriate to the type of the resin material **103r**. For example, the exposure amount may be from 100 mJ/cm² to 500 mJ/cm².

The photomask PM1 includes an opaque portion SH that blocks the light L0 and transmissive portions TR that allow the light L0 to pass. As illustrated in FIG. 9B, when the resin material **103r** is, for instance, a positive photosensitive material, then the opaque portion SH is arranged over positions where the resin material **103r** is to remain and the transmissive portions TR are arranged over positions where the resin material **103r** is to be removed. Specifically, the photomask PM1 may have the opaque portion SH extending in the second direction Y and arranged in plurality with spacing along the first direction X, and the transmissive portions TR may be arranged between pieces of the opaque portion SH. Here, the regions under the transmissive portions TR correspond to where the lower electrodes **111**, **121** are to be formed, and the region below the opaque portion SH corresponds to where the gap G is to be formed.

Exposure through the photomask PM1 causes the light L0 to pass only through the transmissive portions TR and reach the resin material **103r** below the transmissive portions TR. The solubility to developing fluid of the resin material **103r** that has been exposed to the light L0 is increased.

c. Developing

Next, as illustrated in FIG. 9C, developing is performed to form the convex layer **103** by removing photosensitive regions of the resin material **103r**. The specific developing method may involve, for example, soaking the substrate **101**, after exposure, in a developing fluid such as an organic solvent or alkaline solution that dissolves the resin material **103** that has been exposed. Afterward, the substrate **101** may be washed with a rinsing liquid such as pure water. As a result, the convex layer **103** is formed over the inter-layer insulation layer **102**, and is shaped so as to extend in the second direction Y. The convex layer **103** may also be cured after developing, in order to improve the density of the convex layer **103**, improve the adhesion with the inter-layer insulation layer **102**, remove dross, and so on. Specifically, the convex layer **103** may be heated, after developing, on a hot plate, in a hot-air drying oven, under an infra-red lamp, or the like. The curing temperature and curing time may be set as appropriate in accordance with the resin material **103r**, and may be, for example, from 150° C. to 250° C. and from 30 minutes to 120 minutes.

4. Remarks

In the panel **10**, at least a part of the bottom face **105FB** of the partition wall **105** is positioned higher than the bottom faces **105SB** of the partition wall **105**. As a result, sinking of the top face **105T** is constrained at least at the part of the bottom face **105FP** positioned higher than the bottom faces **105SB**. Accordingly, irregularities in the top face **105T** of the partition wall **105** are reduced. As such, this enables a reduction in the formation of cracks in upper layers such as the electron transport layer **106** and the upper electrode **107**.

Also, in the panel **10**, not only the organic light-emitting layers **113**, **123** but also the hole transport layers **112**, **122** are

formed using a wet process. As such, constraining sinking of the top face **105T** of the partition wall **105** makes ink less likely to run during formation of the hole transport layers **112**, **122**, improves formation precision for the hole transport layers **112**, **122**, and further stabilizes the quality of the panel **10**.

In addition, in the panel **10**, a central part of the bottom face **105FB** in the first direction X is beneficially arranged at a higher position than the bottom faces **105SB**. In a situation where the convex layer **103** is absent, sinking of the top face **105T** of the partition wall **105** becomes greatest at the central part, which is in the midway between the lower electrodes **111**, **121**. As such, positioning the central portion of the bottom face **105FB** in the first direction X, where the top face is most prone to sinking, higher than the bottom faces **105SB** enables sinking of the top face **105T** to be effectively constrained.

<Variations>

The panel **10** and the manufacturing method of the panel **10** have been described above as examples of implementation of the present disclosure. However, with the exception of components having essential characteristics, no limitation is intended to the above explanations. Variations are described below as other aspects of the disclosure. In the following, components identical to those described above use the same reference signs and explanations thereof are simplified or omitted.

(1) Inter-Layer Insulation Layer and Convex Layer Integration

In the embodiment, the inter-layer insulation layer **102** and the convex layer **103** are described as being distinct layers. However, the inter-layer insulation layer and the convex layer may also be a single layer. FIG. **10** is a schematic cross-sectional diagram illustrating an inter-layer insulation layer **202** pertaining to this variation. The inter-layer insulation layer **202** is formed from a resin material, and is disposed along the top face of the substrate **101**. In addition, the inter-layer insulation layer **202** has a top face shaped in conformity with the top face of the substrate **101**. The inter-layer insulation layer **202** includes a planar portion **202b** on which the lower electrodes **111**, **121** are disposed, and a convex portion **202a** over the planar portion **202b** corresponding to the gap G, and protruding upward, higher than top faces of the lower electrodes **111**, **121**.

Here, a part of the foundation of the partition wall **105**, made up of the inter-layer insulation layer **202** having the convex portion **202a**, below the first portion **105F** protrudes upward higher than parts of the foundation below the second portions **105S**. As a result, in the panel **10** equipped with the inter-layer insulation layer **202**, at least part of the bottom face **105FB** is raised above the bottom faces **105SB**.

The following may be used as a formation method for the inter-layer insulation layer **202**, for example. FIGS. **11A**, **11B**, and **11C** are schematic cross-sectional diagrams illustrating the formation method for the inter-layer insulation layer **202**. First, as illustrated in FIG. **11A**, a resin material **202r** is applied over the substrate **101** so as to have a top face shaped to conform to the top face of the substrate **101**, prior to forming the lower electrodes **111**, **121**. For example, the resin material **202r** may be applied with sufficient thickness to cover irregularities in the TFT layer. The resin material **202r** is a positive photosensitive material, identical to resin material **103r**.

Next, as illustrated in FIG. **11B**, a portion of the resin material **202r** is made semi-photosensitive through a photolithography method using a half-tone mask **PM2**. Specifically, for example, the resin material **202r** may be exposed

through the half-tone mask **PM2**, which has semi-transmissive portions **HTR** replacing the transmissive portions **TR** of the photomask **PM1**. Accordingly the light **L0** is attenuated by the semi-transmissive portions **HTR** during exposure, enabling the resin material **202r** under the semi-transmissive portions **HTR** to be made semi-photosensitive. Upper parts of the portions of the resin material **202r** that have been made semi-photosensitive in the thickness direction (i.e., the Z direction in FIG. **11B**) become photosensitive and more soluble in developing fluid. However, lower parts of the portions of the resin material **202r** that have been made semi-photosensitive in the thickness direction remain not soluble in the developing fluid.

Subsequently, as illustrated in FIG. **11C**, the resin material **202r**, now semi-photosensitive, is developed. Thus, in the portions made semi-photosensitive, only the upper parts in the thickness direction are removed, thereby enabling a reduction in thickness. Accordingly, the inter-layer insulation layer **202** is formed to include the planar portion **202b** having the top face shaped in conformity with the top face of the substrate **101**, and the convex portion **202a** protruding upward with respect to the planar portion **202b**.

The following may also be used as a formation method for the inter-layer insulation layer **202**, for example. FIGS. **12A**, **12B**, and **12C** are schematic cross-sectional diagrams illustrating the formation method for the inter-layer insulation layer **202**. First, as illustrated in FIG. **12A**, the resin material **202r** is applied over the substrate **101** so as to have a top face shaped to conform to the top face of the substrate **101**, prior to forming the lower electrodes **111**, **121**.

Next, as illustrated in FIG. **12B**, a photolithography method using dry etching is employed to reduce the thickness of a portion of the resin material. Specifically, the photolithography method is first used to apply a photoresist **PR** only to a portion where the convex portion **202a** is to be formed. Here, the material of the photoresist **PR** is beneficially a positive photosensitive material, similarly to the resin material **202r**. As a result, the possibility of a portion forming the convex portion **202a** becoming photosensitive is decreased. Then, a compound gas of oxygen and plasma-fied tetrafluoromethane (CF_4) may be used to remove the upper part of the resin material **202r** where the photoresist **PR** is not disposed.

Subsequently, as illustrated in FIG. **11C**, peeling the photoresist **PR** from the substrate **101** using a peeling solution or the like enables the inter-layer insulation layer **202** to be formed with the planar portion **202b** and the convex portion **202a** as described above.

In addition, the remainder of the manufacturing method of the panel **10** may involve forming the lower electrodes **111**, **121** such that the first lower electrode **111** and the second lower electrode **121** are respectively formed with thickness that is less than a difference in thickness between the convex portion **202a** and the planar portion **202b**, over parts of the planar portion **202b** each at a difference side of the convex portion **202a** in the first direction X. The rest proceeds as described in the embodiment.

(2) Lamination and Formation Order of Inter-Layer Insulation Layer and Convex Layer

In the embodiment, the inter-layer insulation layer **102** and the convex layer **103** are formed in the stated order and are therefore laminated in the stated order. However, the lamination and formation order may be reversed. FIG. **13** is a schematic cross-sectional diagram illustrating an inter-layer insulation layer **302** pertaining to this variation. In the

present variation, the convex layer 103 is disposed directly over the substrate 101, between the substrate 101 and the first portion 105F.

The inter-layer insulation layer 302 is formed from a resin material, is arranged over the substrate 101 and the convex layer 103, and is shaped to have a top face that conforms to the top face of the substrate 101 and the top face of the convex layer 103. Also, the lower electrodes 111, 121 are arranged over the inter-layer insulation layer 302.

The thickness of the convex layer 103 is greater than the thickness of the lower electrodes 111, 121. The inter-layer insulation layer 302 has a top face shaped in conformity with the top face of the substrate 101 and the top face of the convex layer 103. As such, a part of the inter-layer insulation layer 302, which is the foundation of the partition wall 105, below the first portion 105F protrudes upward higher than parts of the inter-layer insulation layer 302 below the second portions 105S. As a result, in the panel 10 equipped with the inter-layer insulation layer 302, at least part of the bottom face 105FB is raised above the bottom faces 105SB.

The formation method for the inter-layer insulation layer 302 may, for example, involve using a resin material to form the convex layer 103 with a shape extending in the second direction Y over the substrate 101 prior to forming the lower electrodes 111, 121, and using the same resin material as the convex layer 103 to form the inter-layer insulation layer 302 over the substrate 101 and the convex layer 103 with a top face shaped in conformity with the top face of the substrate 101 and the top face of the convex layer 103. Here, for example, the inter-layer insulation layer 302 may be formed with a thickness on the same order as the thickness of the convex layer 103. The thickness of the convex layer 103 and the thickness of the inter-layer insulation layer 302 may be determined as appropriate for the shape and specifications of the panel 10. However, when the thickness of the convex layer 103 is, for example, from 0.5 μm to 1 μm , the thickness of the inter-layer insulation layer 302 is from 3 μm to 5 μm . Specifically, the formation method for the convex layer 103 and the inter-layer insulation layer 302 may be identical to the previously-described formation method for the inter-layer insulation layer 102 and the convex layer 103.

In addition, the ensuing manufacturing method of the panel 10 may involve forming the lower electrodes 111, 121 such that the first lower electrode 111 and the second lower electrode 121 are respectively formed with thickness that is less than the thickness of the convex layer 103, over parts of the inter-layer insulation layer 302 each at a different side of the convex portion 103 in the first direction X. The rest proceeds as described in the embodiment.

(3) Lamination and Formation Order of Convex Layer and Lower Electrode

In the embodiment, the convex layer 103 and the lower electrodes 111, 121 are formed in the stated order and are therefore laminated in the stated order. However, the lamination and formation order may be reversed. FIG. 14 is a schematic perspective view illustrating a convex layer 403 pertaining to this variation. FIG. 14, like FIG. 5, illustrates a state before forming the partition wall 105. In the present variation, the partition wall 105 and the respective layers formed after the partition wall 105 are identical to the embodiment.

Similarly to convex layer 103, convex layer 403 is formed from an electrically resistant material, is disposed between the substrate 101 and the first portion 105F, and is shaped to extend along the second direction Y. The thickness of the convex layer 403 is greater than the thickness of the lower electrodes 111, 121 and the thickness of the pixel insulation

layer 104. In addition, the convex layer 403 and the pixel insulation layer 104 are formed integrally as a single layer, and thus, the convex layer 403 is formed after the lower electrodes 111, 121. Further, the convex layer 403 is disposed so as to cover neighboring ends of the first lower electrode 111 and the second lower electrode 121.

The thickness of the convex layer 403 is greater than the thickness of the lower electrodes 111, 121. As such, a part of the foundation of the partition wall 105, made up of the lower electrodes 111, 121 and the convex layer 403, below the first portion 105F protrudes higher than parts of the foundation below the second portions 105S (above the lower electrodes 111, 121). As a result, in the panel 10 equipped with the convex layer 403, at least part of the bottom face 105FB is raised above the bottom faces 105SB.

The formation method for the convex layer 403 may involve, for example first using an electrically insulating material to form an insulating layer on the top face of the substrate 101 having the lower electrode columns 111C, 121C formed thereon, prior to forming the partition wall 105, so that the insulating layer has greater thickness than the lower electrodes 111, 121. Next, a photolithography method is used to remove parts of the insulating layer over the lower electrodes 111, 121, and to form the convex layer 403 extending in the second direction Y between the first lower electrode column 111C and the second lower electrode column 121C and the pixel insulation layer 104 extending in the first direction X and having less thickness than the convex layer 403 between pairs of the first lower electrodes 111 and pairs of the second lower electrodes 121. Here, a half-tone mask may be used in the photolithography method to form the pixel insulation layer 104 with less thickness than the convex layer 403. The specific method may be identical to the formation method of the inter-layer insulation layer 202 illustrated in FIG. 11.

As described above, forming the convex layer 403 and the pixel insulation layer 104 as a single layer enables the convex layer 403 to be formed at the same time as the pixel insulation layer 104 and enables any decrease in manufacturing efficiency caused by the addition of the convex layer 403 to be constrained.

(4) Partition Wall Foundation Layers

In the embodiment, the convex layer 103, the pixel insulation layer 104, and the lower electrodes 111, 121 form a foundation of the partition wall 105. However, no such limitation is intended. FIG. 15 is a schematic cross-sectional diagram illustrating a hole injection layer 509 pertaining to this variation. In the present variation, a first lower electrode 511 and a second lower electrode 511, respectively corresponding to the first metal layer 111a and the second metal layer 121a of the embodiment, and a hole injection layer 509 serving as a replacement member for the first oxide layer 111b and the second oxide layer 121b of the embodiment, are provided. As such, in this variation, the hole injection layer 509 is the foundation for the partition wall 105.

The hole injection layer 509 uses the same material and has the same function as the first oxide layer 111b and the second oxide layer 121b, and may be termed a cover layer disposed across the entirety of the convex layer 103, the first lower electrode 511, and the second lower electrode 521.

In addition, the hole injection layer 509 is sufficiently thin (e.g., the thickness of the hole injection layer 509 is on the order of a few tens of nm when the thicknesses of the first lower electrode 511, the second lower electrode 521, and the convex layer are from a few hundred nm to a few μm) to cover irregularities on the top face of the convex layer 103 and on the top faces of the first lower electrode 511 and the

second lower electrode **521**. That is, a part of the foundation of the partition wall **105** below the first portion **105F** protrudes upward higher than parts of the foundation below the second portions **105S**. As a result, the panel **10** equipped with the hole injection layer **509** also has at least part of the bottom face **105FB** raised above the bottom faces **105SB**.

In addition, the formation method for the hole injection layer **509** may, for example, involve first forming only a metal film as formed in the formation method of the lower electrodes **111**, **121** of the embodiment, and then using patterning to form the first lower electrode **511** and the second lower electrode **521**. Next, the hole injection layer **509** is yielded by forming a thin film of metal oxide according to the method of the embodiment.

Also, as illustrated in FIG. **15**, the first lower electrode **511** and the second lower electrode **521** may be formed to be in contact with inclined surfaces of the convex layer **103**. In such a situation, electrical insulation is also secured between the first lower electrode **511** and the second lower electrode **521** by the convex layer **103**. Further, having this shape tolerance widens the range of tolerable error in the patterning area of the first lower electrode **511** and the second lower electrode **521**, and imparts some slack in alignment precision.

(5) Other

In the panel **10**, the color of emitted light of the first organic light-emitting layer **113** and the color of emitted light of the second organic light-emitting layer **123** differ. However, no such limitation is intended. The color of emitted light of the first organic light-emitting layer **113** and the color of emitted light of the second organic light-emitting layer **123** may also be identical. Specifically, for example, the color of emitted light of all organic light-emitting layers including the first organic light-emitting layer and the second organic light-emitting layer may be white such as in an organic electroluminescence display panel using a color modulation scheme or a color filter scheme. In addition, for example, the partition wall may be shaped as a lattice (i.e., a pixel bank) individually partitioning each lower electrode, and members corresponding to the convex layer **103** may be disposed in gaps (i.e., gaps between lower electrodes aligned in the Y direction of the panel **10**) between sub-pixels emitting light of the same color. That is, in the panel **10**, a cross-section along each sub-pixel column, which is a line of sub-pixels emitting the same color, may also have the configuration illustrated in FIG. **3A** instead of the configuration illustrated in FIG. **3B**. As described above, even if the color of emitted light of the first organic light-emitting layer and the color of emitted light of the second organic light-emitting layer are identical, constraining sinking of the top surface of the partition wall therebetween prevents ink from running across the partition wall, enabling improvements to the formation precision in terms of organic light-emitting layer thickness.

Here, configuring the partition wall as described above, in a situation as in the panel **10** where the color of emitted light of the first organic light-emitting layer **113** and the color of emitted light of the second organic light-emitting layer **123** are different, constrains the occurrence of not only formation degradation in terms of film formation thickness but also of mixing (color combination) of ink including different organic light-emitting materials. That is, quality degradation of the panel **10** may be suppressed by preventing faulty pixels P and the like.

Also, in FIG. **5**, the pixel insulation layer **104** is arranged over the convex layer **103**. However, no such limitation is

intended. The pixel insulation layer **104** may be provided only between pairs of the convex layer **103**.

In addition, in the panel **10**, as illustrated in FIG. **2**, the direction of extension of the pixel insulation layer **104** is a major axis (X) direction of the panel **10** and the direction of extension of the partition wall **105** is a minor axis (Y) direction of the panel **10**. However, the respective directions of extension of the pixel insulation layer and the partition wall may be reversed. Also, the direction of extension of the pixel insulation layer and of the partition wall may be a direction unrelated to the shape of the panel **10**. Furthermore, the pixel insulation layer and the partition wall may intersect at an angle other than 90°, provided that intersection occurs. Also, in such a situation, the direction of arrangement of the sub-pixel columns CR, CG, and CB may be parallel to the direction of extension of the partition wall.

In addition, in the panel **10**, the material of the first oxide layer **111b**, the second oxide layer **121b**, and the hole injection layer **509** having the capacity to inject holes is a metal oxide material. However, no such limitation is intended. An organic material such as PEDOT (a compound of polythiophene and polystyrene acid) may also be used. In such a situation, the hole injection layer may be formed using a wet process.

Also, in the panel **10**, the hole transport layers **112**, **122** are formed using a wet process. However, no such limitation is intended. A dry process may also be used. In addition, when a dry process is used, the hole transport layers **112**, **122** may be continuous with one another crossing the partition wall **105**, similarly to the hole injection layer **509**.

Further, in the panel **10**, each of the electron transport layer **106** and the upper electrode **107** is a continuous layer crossing the partition wall **105**. However, for example, a wet process may be used to arrange the electron transport layer **106** and the upper electrode **107** independently on each sub-pixel column CR, CG, and CB. In addition, for example, the electrodes and functional layers making up the organic electroluminescence elements may be independently arranged in each of the sub-pixels **100R**, **100G**, and **100B**.

Also, in the panel **10**, the image display face is described as rectangular. However, no such limitation is intended to the shape of the image display face. For instance, the image display face may be triangular, square, pentagonal or otherwise polygonal, round, elliptical, or a combination of these shapes. Here, an image display region (i.e., arrangement range of the sub-pixels **100R**, **100G**, and **100B**) of the image display face may be shaped to suit the image display face, or may have a different shape. For example, the image display region may be elliptical or similar while the image display face is rectangular. Furthermore, the shape of the substrate may correspond to the shape of the image display face, and the shape of a face other than the image display face may be different than the image display face.

Also, in the panel **10**, the lower electrodes **111**, **121** are rectangular plate-shaped members. However, no such limitation is intended. The lower electrodes **111**, **121** may also have a polygonal plate shape, an elliptical plate shape, or a combination thereof. In addition, the lower electrodes **111**, **121** may have concavities in conformity with the shape of contact holes in the inter-layer insulation layer **102**.

Also, in the panel **10**, the sub-pixels **100R**, **100G**, and **100B** are aligned according to the respective red, green, and blue emitted light. However, no such limitation is intended to the color of light emitted by the sub-pixels. For example, all light may be uniformly red, or a combination of four colors such as red, green, blue, and yellow may be used. In addition, the sub-pixels are not limited to being provided as

one per color in each pixel P, and may also be provided in plurality. Also, the arrangement of the sub-pixels in the pixels P is not limited to red, green, and blue in order as illustrated in FIG. 2. A permutation thereof may also be used.

Also, in the panel 10, the lower electrodes 111, 121 serve as anodes and the upper electrode 107 serves as a cathode. However, no such limitation is intended. An opposite configuration, in which the lower electrodes serve as cathodes and the upper electrode serves as an anode, may also apply. In such a situation, the lamination order of the hole injection layer, the hole transport layer, and the electron transport layer may be adjusted as appropriate.

Also, in FIG. 2, only the sub-pixels 100R, 100G, and 100B are arranged between pairs of the partition wall 105. However, a bus bar (i.e., an auxiliary electrode) may also be arranged there in order to reduce the influence of voltage drops caused by resistive components of the upper electrode 107.

Also, the panel 10 is equipped with a laminated structure in which, for example, an electron injection layer, an inhibition layer, a buffer layer, and so on may also be provided. In addition, a subset of the above-described components may also be omitted. Further, an electron injection and transport layer, for instance, may physically be a single layer having a plurality of functions. Also, a sealing plate made of a glass material or the like may be disposed over the thin film sealing layer 108 as a protective member for the other components. Here, a space between the thin film sealing layer 108 and this sealing plate may, for example, be filled with a curable resin material, thus improving adhesion between the thin film sealing layer 108 and the sealing plate. Also, color filters may be arranged at positions of the sealing plate corresponding to the sub-pixels 100R, 100G, and 100B to correct the color of emitted light. In addition, a black matrix may be arranged at positions corresponding to positions between the sub-pixels 100R, 100G, and 100B on the sealing plate and at a peripheral region of the sealing plate in order to constrain reflection of outside light and to improve contrast.

Also, the panel 10 is described as employing top emission and an active matrix scheme. However, no such limitation is intended. For instance, bottom emission and a passive matrix scheme may also be employed.

An organic electroluminescence display panel and organic electroluminescence display panel manufacturing method pertaining to the present disclosure are widely applicable to manufacturing display panels for use in electronic devices such as televisions, personal computers, mobile terminals, commercial displays, and so on.

Although the technology pertaining to the present disclosure has been fully described by way of examples with reference to the accompanying drawings, it is to be noted that various changes and modifications will be apparent to those skilled in the art. Therefore, unless such changes and modifications depart from the scope of the present disclosure, they should be construed as being included therein.

The invention claimed is:

1. An organic electroluminescence display panel, comprising:

- a substrate;
- a first lower electrode and a second lower electrode disposed over the substrate and spaced away from one another in a first direction along a top face of the substrate by a gap;
- a partition wall comprising an electrically insulating material and separating a space above the first lower

electrode and a space above the second lower electrode from one another, the partition wall including a first portion disposed over the gap and two second portions each of which is disposed over a different one of the first lower electrode and the second lower electrode, the first portion disposed between the two second portions in the first direction;

a convex layer made of an electrically insulating material between the substrate and the first portion, the convex layer having greater thickness than the first lower electrode and the second lower electrode;

a first organic light-emitting layer and a second organic light-emitting layer respectively disposed in the space above the first lower electrode and the space above the second lower electrode; and

an upper electrode extending over the first organic light-emitting layer and the second organic light-emitting layer, wherein

at least a part of a bottom face of the first portion is positioned higher than a bottom face of at least one of the two second portions,

the convex layer comprises cured resin,

the partition wall comprises cured resin, and

the part of the bottom face of the first portion is directly on a top surface of the convex layer.

2. The organic electroluminescence display panel according to claim 1, wherein

in the first direction, a central part of the bottom face of the first portion is positioned higher than the bottom face of the at least one of the two second portions.

3. The organic electroluminescence display panel according to claim 1, further comprising:

an inter-layer insulating layer comprising a resin material and disposed over the substrate, a shape of a top face of the inter-layer insulating layer in conformity with a shape of the top face of the substrate, wherein

the first lower electrode, the second lower electrode, and the convex layer are disposed over the inter-layer insulating layer.

4. The organic electroluminescence display panel according to claim 1, further comprising:

an inter-layer insulating layer comprising a resin material and disposed over the substrate, a shape of a top face of the inter-layer insulating layer in conformity with a shape of the top face of the substrate, wherein

the inter-layer insulating layer includes a planar portion on which the first lower electrode and the second lower electrode are disposed and the convex layer.

5. The organic electroluminescence display panel according to claim 1, wherein

in a second direction that is along the top face of the substrate and that is perpendicular to the first direction, the first lower electrode is provided in plurality to form a line of first lower electrodes, and the second lower electrode is provided in plurality of form a line of second lower electrodes,

the first organic light-emitting layer extends in the second direction over the line of first lower electrodes, and the second organic light-emitting layer extends in the second direction over the line of second lower electrodes, and

the partition wall extends in the second direction between the first organic light-emitting layer and the second organic light-emitting layer, and in any cross-section taken along the second direction, the part of the bottom

face of the first portion is positioned higher than the bottom face of the at least one of the two second portions.

6. The organic electroluminescence display panel according to claim 5, wherein 5

the convex layer extends in the second direction, and the convex layer has greater thickness than the first lower electrodes and the second lower electrodes.

7. The organic electroluminescence display panel according to claim 6, further comprising: 10

a pixel insulation layer comprising an electrically insulating material, extending in the first direction, and disposed between electrodes adjacent in the second direction, the electrodes adjacent in the second direction comprising a combination of two first lower electrodes and a combination of two second lower electrodes, wherein 15

the pixel insulation layer has greater thickness than the first lower electrodes and the second lower electrodes, and has smaller thickness than the convex layer. 20

8. The organic electroluminescence display panel according to claim 7, wherein

the convex layer and the pixel insulation layer form a single layer.

9. The organic electroluminescence display panel according to claim 1, wherein 25

a color of light emitted by the first organic light-emitting layer differs from a color of light emitted by the second organic light-emitting layer.

* * * * *

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专利名称(译)	有机电致发光显示板及其制造方法		
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申请(专利权)人(译)	JOLED INC.		
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[标]发明人	NENDAI KENICHI		
发明人	NENDAI, KENICHI		
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摘要(译)

一种有机EL显示面板，包括：基板；第一下部电极和第二下部电极，设置在基板上，第一方向上具有间隙；将第一下电极上方的空间和第二下电极上方的空间彼此分开的壁；分别配置在空间内的有机发光层；以及在有机发光层上延伸的上电极。该壁包括设置在间隙上的第一部分和两个第二部分，每个第二部分设置在第一下电极和第二下电极中的不同的一个上。第一部分在第一方向上位于两个第二部分之间，并且第一部分的底面的至少一部分位于比第二部分的底面高的位置。

